

19.7 Serial Programming Characteristics

Figure 19-4. Serial Programming Waveforms

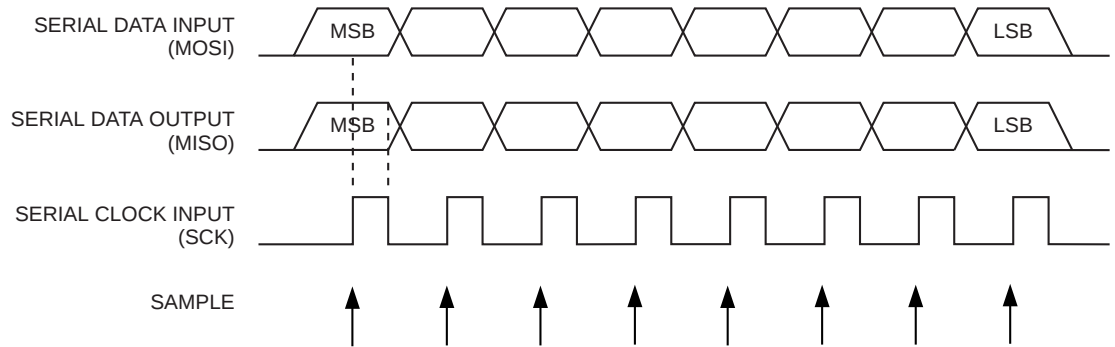


Figure 19-5. Serial Programming Timing

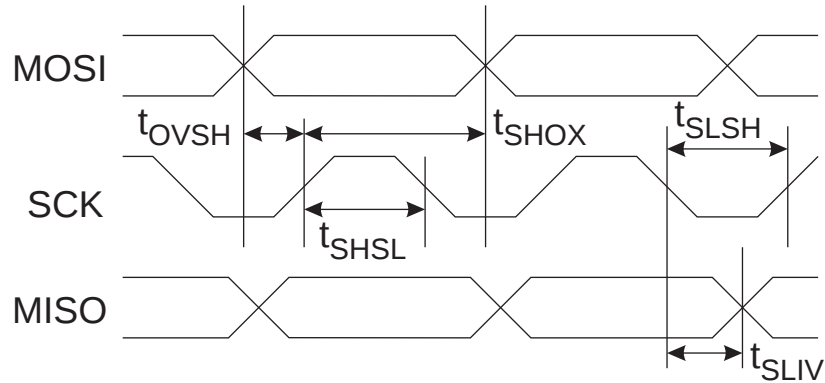


Table 19-8. Serial Programming Characteristics, $T_A = -40^{\circ}\text{C}$ to $+85^{\circ}\text{C}$, $V_{CC} = 1.8 - 5.5\text{V}$ (Unless Otherwise Noted)

Symbol	Parameter	Min	Typ	Max	Units
$1/t_{CLCL}$	Oscillator Frequency (ATtiny261V/461V/861V)	0		4	MHz
t_{CLCL}	Oscillator Period (ATtiny261V/461V/861V)	250			ns
$1/t_{CLCL}$	Oscillator Frequency (ATtiny261/461/861, $V_{CC} = 4.5 - 5.5\text{V}$)	0		20	MHz
t_{CLCL}	Oscillator Period (ATtiny261/461/861, $V_{CC} = 4.5 - 5.5\text{V}$)	50			ns
t_{SHSL}	SCK Pulse Width High	$2 t_{CLCL}^{(1)}$			ns
t_{SLSH}	SCK Pulse Width Low	$2 t_{CLCL}^{(1)}$			ns
t_{OVSH}	MOSI Setup to SCK High	t_{CLCL}			ns
t_{SHOX}	MOSI Hold after SCK High	$2 t_{CLCL}$			ns
t_{SLIV}	SCK Low to MISO Valid			100	ns

Note: 1. $2 t_{CLCL}$ for $f_{ck} < 12\text{ MHz}$, $3 t_{CLCL}$ for $f_{ck} \geq 12\text{ MHz}$

19.8 Parallel Programming Characteristics

Figure 19-6. Parallel Programming Timing, Including some General Timing Requirements

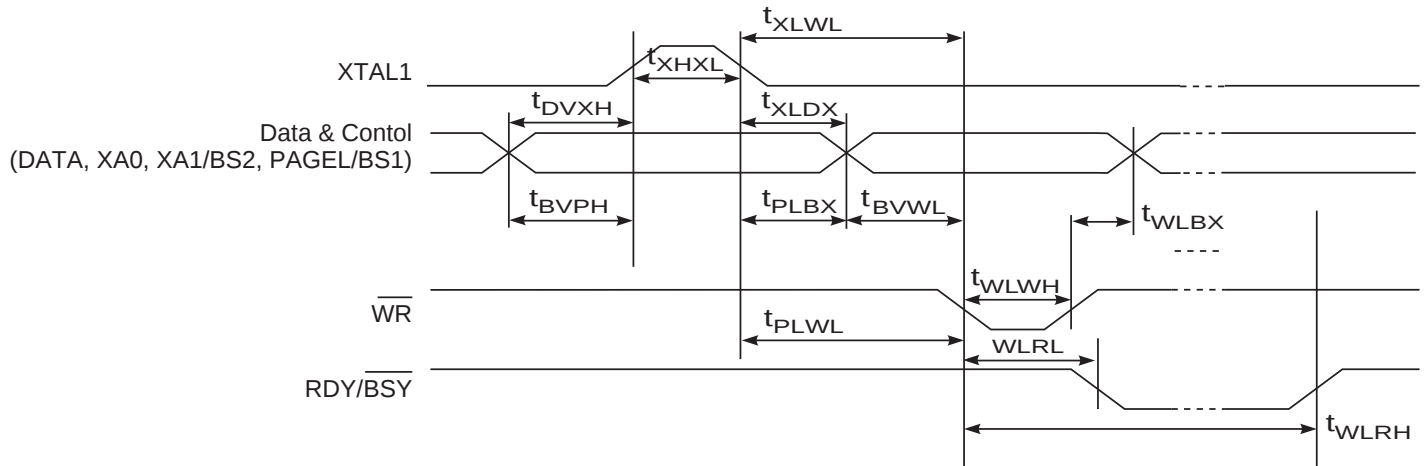
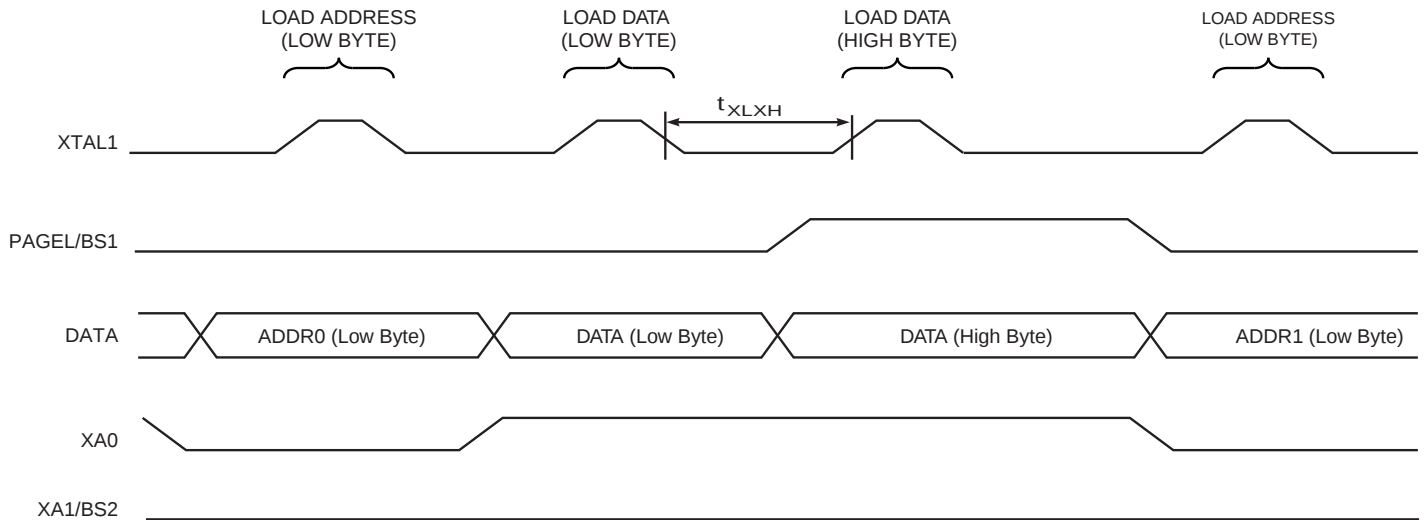
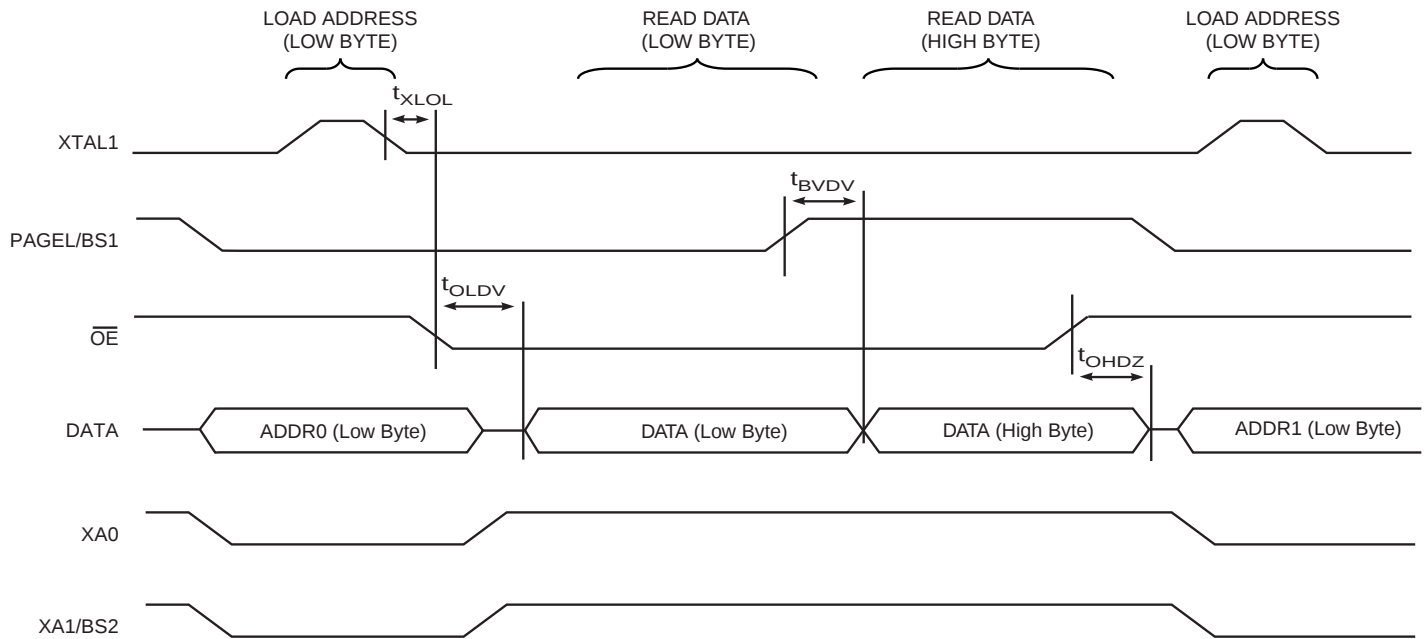


Figure 19-7. Parallel Programming Timing, Loading Sequence with Timing Requirements



Note: The timing requirements shown in Figure 19-6 (i.e., t_{DVXH} , t_{XHL} , and t_{XLDX}) also apply to loading operation.

Figure 19-8. Parallel Programming Timing, Reading Sequence (within the Same Page) with Timing Requirements



Note: The timing requirements shown in Figure 19-6 (i.e., t_{DVXH} , t_{XHXL} , and t_{XLDX}) also apply to reading operation.

Table 19-9. Parallel Programming Characteristics, $V_{CC} = 5V \pm 10\%$

Symbol	Parameter	Min	Typ	Max	Units
V_{PP}	Programming Enable Voltage	11.5		12.5	V
I_{PP}	Programming Enable Current			250	μA
t_{DVXH}	Data and Control Valid before XTAL1 High	67			ns
t_{XLXH}	XTAL1 Low to XTAL1 High	200			ns
t_{XHXL}	XTAL1 Pulse Width High	150			ns
t_{XLDX}	Data and Control Hold after XTAL1 Low	67			ns
t_{XLWL}	XTAL1 Low to $\overline{WR}$ Low	0			ns
t_{BVPH}	BS1 Valid before PAGEL High	67			ns
t_{PHPL}	PAGEL Pulse Width High	150			ns
t_{PLBX}	BS1 Hold after PAGEL Low	67			ns
t_{WLBX}	BS2/1 Hold after $\overline{WR}$ Low	67			ns
t_{PLWL}	PAGEL Low to $\overline{WR}$ Low	67			ns
t_{BVWL}	BS1 Valid to $\overline{WR}$ Low	67			ns
t_{WLWH}	$\overline{WR}$ Pulse Width Low	150			ns
t_{WLRL}	$\overline{WR}$ Low to $\overline{RDY/BSY}$ Low	0		1	μs
t_{WLRH}	$\overline{WR}$ Low to $\overline{RDY/BSY}$ High ⁽¹⁾	3.7		4.5	ms
t_{WLRH_CE}	$\overline{WR}$ Low to $\overline{RDY/BSY}$ High for Chip Erase ⁽²⁾	7.5		9	ms
t_{XLOL}	XTAL1 Low to $\overline{OE}$ Low	0			ns

Table 19-9. Parallel Programming Characteristics, $V_{CC} = 5V \pm 10\%$ (Continued)

Symbol	Parameter	Min	Typ	Max	Units
t_{BVDV}	BS1 Valid to DATA valid	0		250	ns
t_{OLDV}	$\overline{OE}$ Low to DATA Valid			250	ns
t_{OHDZ}	$\overline{OE}$ High to DATA Tri-stated			250	ns

- Notes:
1. t_{WLRH} is valid for the Write Flash, Write EEPROM, Write Fuse bits and Write Lock bits commands.
 2. t_{WLRH_CE} is valid for the Chip Erase command.

20. Typical Characteristics

The data contained in this section is largely based on simulations and characterization of similar devices in the same process and design methods. Thus, the data should be treated as indications of how the part will behave.

The following charts show typical behavior. These figures are not tested during manufacturing. During characterisation devices are operated at frequencies higher than test limits but they are not guaranteed to function properly at frequencies higher than the ordering code indicates.

All current consumption measurements are performed with all I/O pins configured as inputs and with internal pull-ups enabled. Current consumption is a function of several factors such as operating voltage, operating frequency, loading of I/O pins, switching rate of I/O pins, code executed and ambient temperature. The dominating factors are operating voltage and frequency.

A sine wave generator with rail-to-rail output is used as clock source but current consumption in Power-Down mode is independent of clock selection. The difference between current consumption in Power-Down mode with Watchdog Timer enabled and Power-Down mode with Watchdog Timer disabled represents the differential current drawn by the Watchdog Timer.

The current drawn from pins with a capacitive load may be estimated (for one pin) as follows:

$$I_{CP} \approx V_{CC} \times C_L \times f_{SW}$$

where V_{CC} = operating voltage, C_L = load capacitance and f_{SW} = average switching frequency of I/O pin.

20.1 Supply Current of I/O modules

The tables and formulas below can be used to calculate the additional current consumption for the different I/O modules in Active and Idle mode. The enabling or disabling of the I/O modules are controlled by the Power Reduction Register. See [“PRR – Power Reduction Register” on page 39](#) for details.

Table 20-1. Additional Current Consumption for the different I/O modules (absolute values).

PRR bit	Typical numbers		
	$V_{CC} = 2V, f = 1MHz$	$V_{CC} = 3V, f = 4MHz$	$V_{CC} = 5V, f = 8MHz$
PRTIM1	65 μA	423 μA	1787 μA
PRTIM0	7 μA	39 μA	165 μA
PRUSI	5 μA	25 μA	457 μA
PRADC	18 μA	111 μA	102 μA

[Table 20-2](#) below can be used for calculating typical current consumption for other supply voltages and frequencies than those mentioned in the [Table 20-1](#) above.

Table 20-2. Additional Current Consumption (percentage) in Active and Idle mode.

PRR bit	Additional Current consumption compared to Active with external clock (see Figure 20-1 on page 198 and Figure 20-2 on page 199)	Additional Current consumption compared to Idle with external clock (see Figure 20-6 on page 201 and Figure 20-7 on page 201)
PRTIM1	26.9 %	103.7 %
PRTIM0	2.6 %	10.0 %
PRUSI	1.7 %	6.5 %
PRADC	7.1 %	27.3 %

It is possible to calculate the typical current consumption based on the numbers from [Table 20-1](#) for other V_{CC} and frequency settings than listed in [Table 20-2](#).

20.1.0.1 Example

Calculate the expected current consumption in idle mode with TIMER0, ADC, and USI enabled at $V_{CC} = 2.0V$ and $F = 1MHz$. From [Table 20-2](#), third column, we see that we need to add 10% for the TIMER0, 27.3 % for the ADC, and 6.5 % for the USI module. Reading from [Figure 20-6 on page 201](#), we find that the idle current consumption is $\sim 0,085 mA$ at $V_{CC} = 2.0V$ and $F=1MHz$. The total current consumption in idle mode with TIMER0, ADC, and USI enabled, gives:

$$I_{CCtotal} \approx 0.085mA \bullet (1 + 0.10 + 0.273 + 0.065) \approx 0.122mA$$

20.2 Active Supply Current

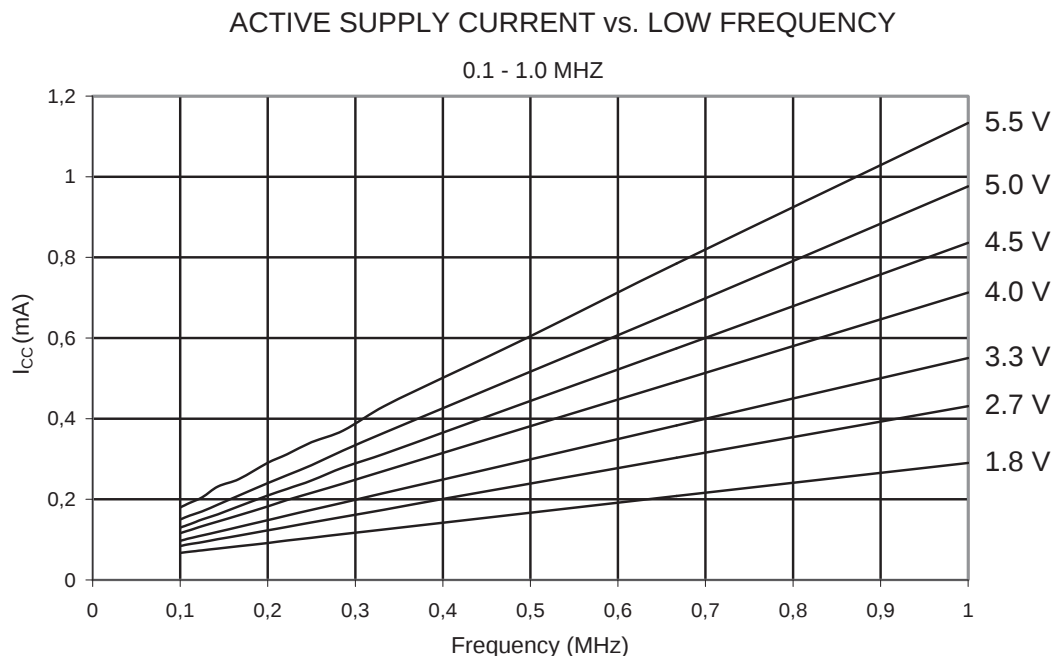
Figure 20-1. Active Supply Current vs. Low Frequency (0.1 - 1.0 MHz)

Figure 20-2. Active Supply Current vs. Frequency (1 - 20 MHz)

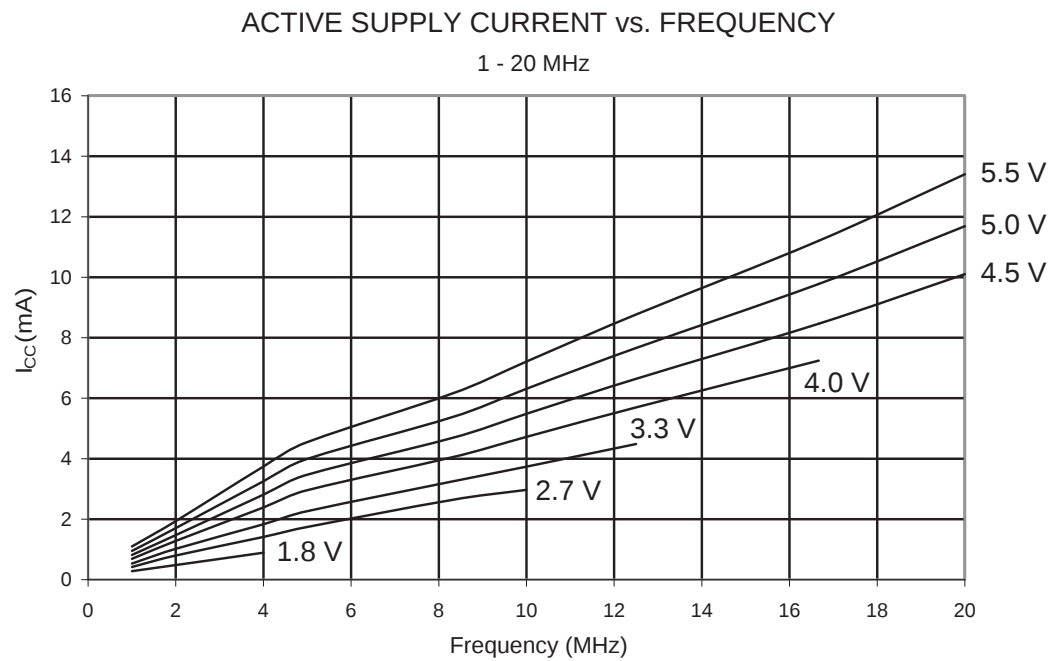


Figure 20-3. Active Supply Current vs. V_{CC} (Internal RC Oscillator, 8 MHz)

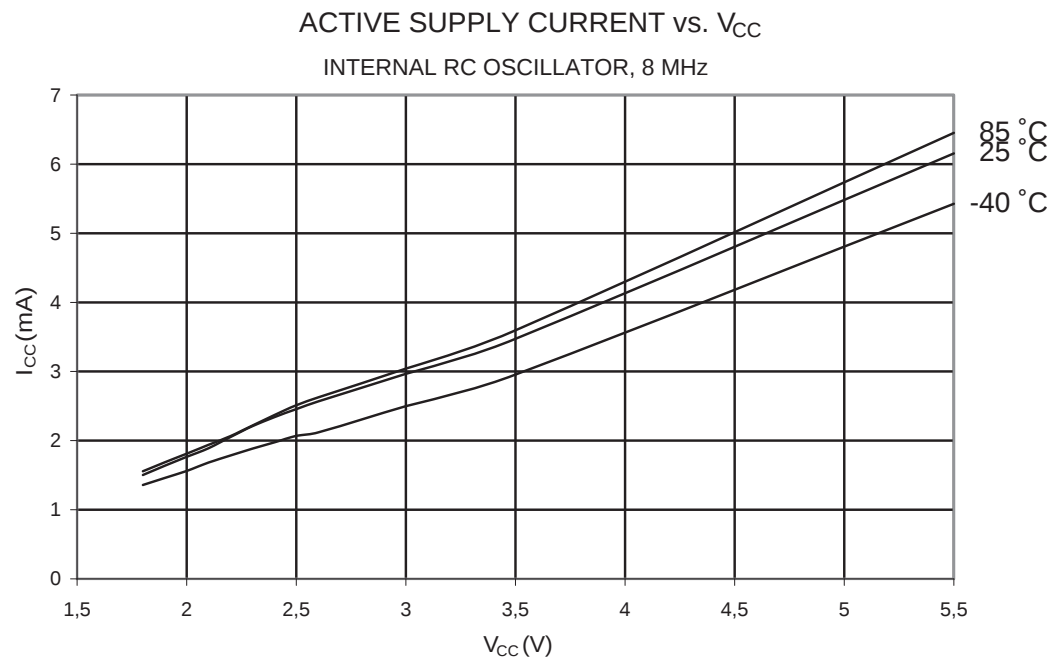
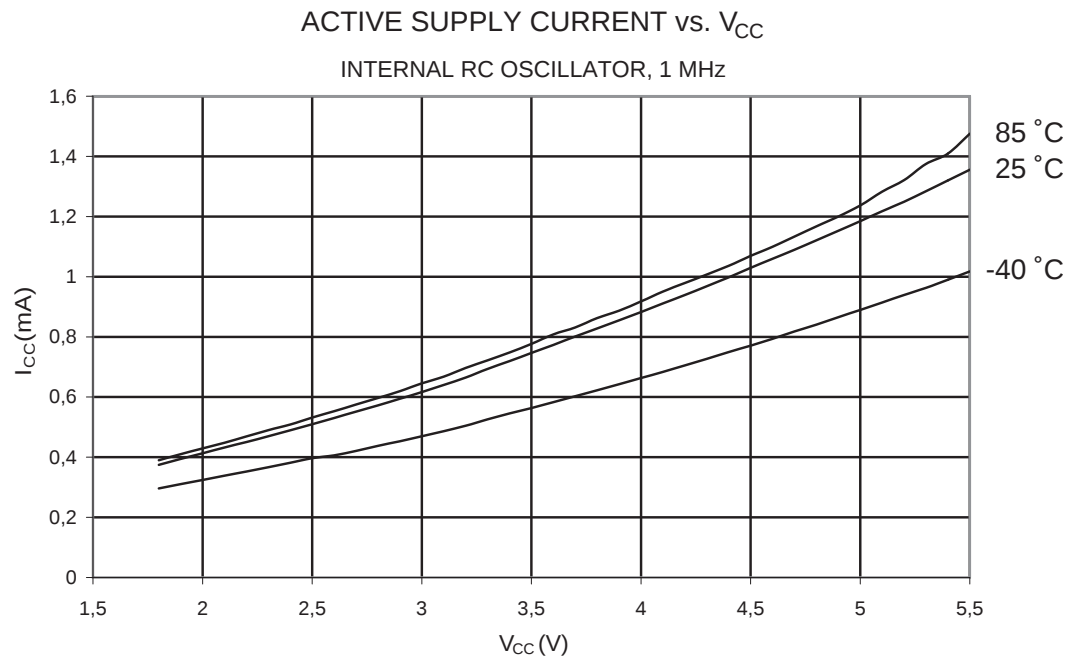
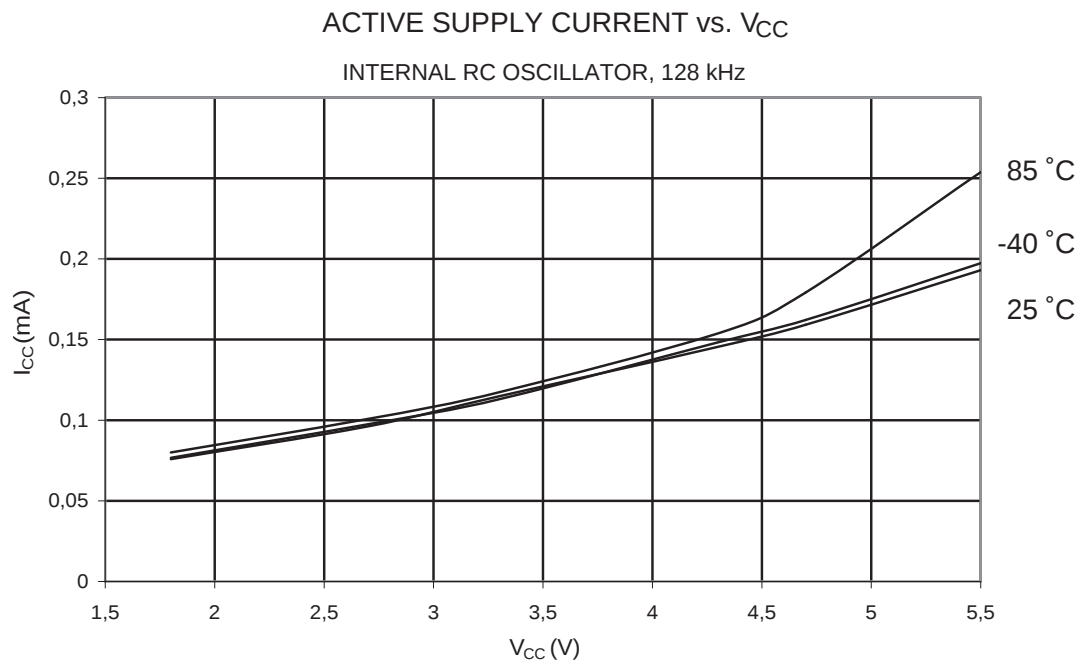


Figure 20-4. Active Supply Current vs. V_{CC} (Internal RC Oscillator, 1 MHz)**Figure 20-5.** Active Supply Current vs. V_{CC} (Internal RC Oscillator, 128 kHz)

20.3 Idle Supply Current

Figure 20-6. Idle Supply Current vs. Low Frequency (0.1 - 1.0 MHz)

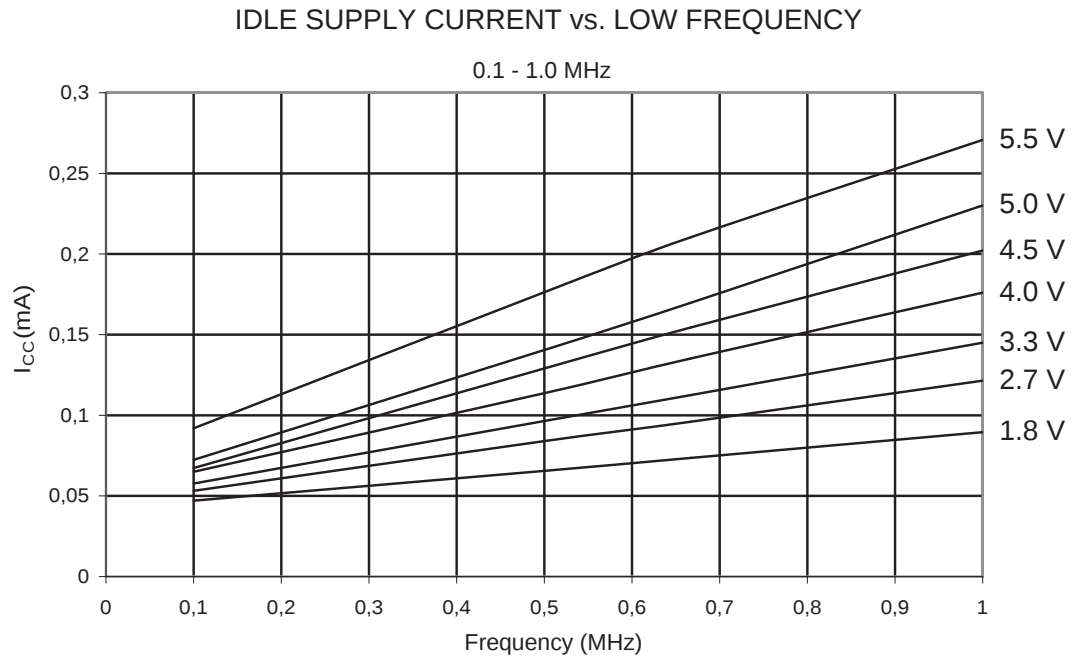


Figure 20-7. Idle Supply Current vs. Frequency (1 - 20 MHz)

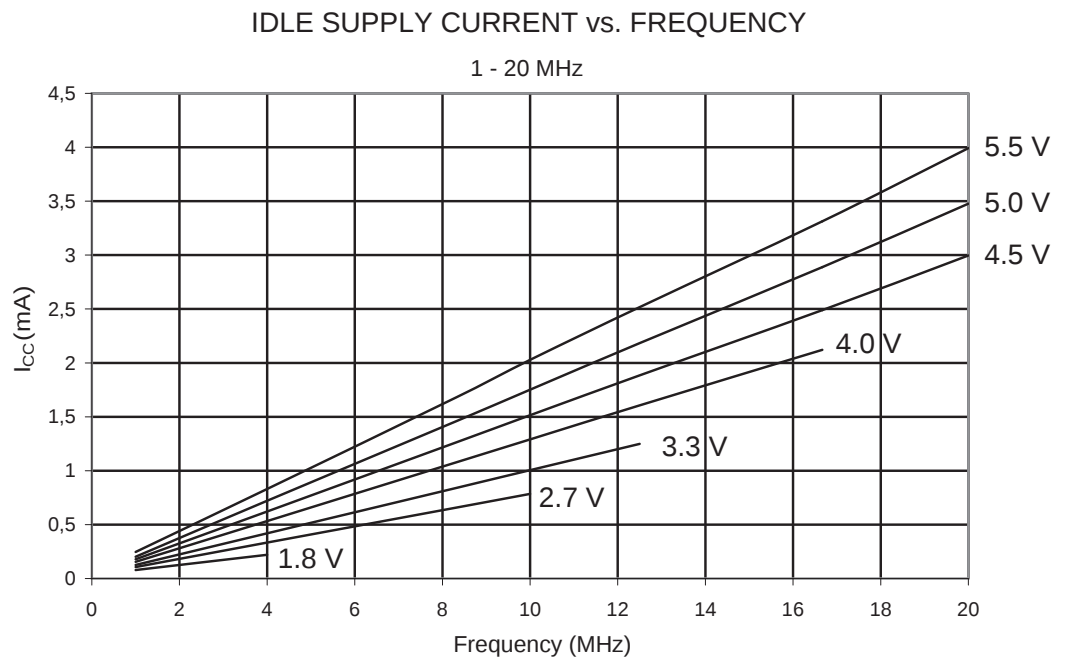


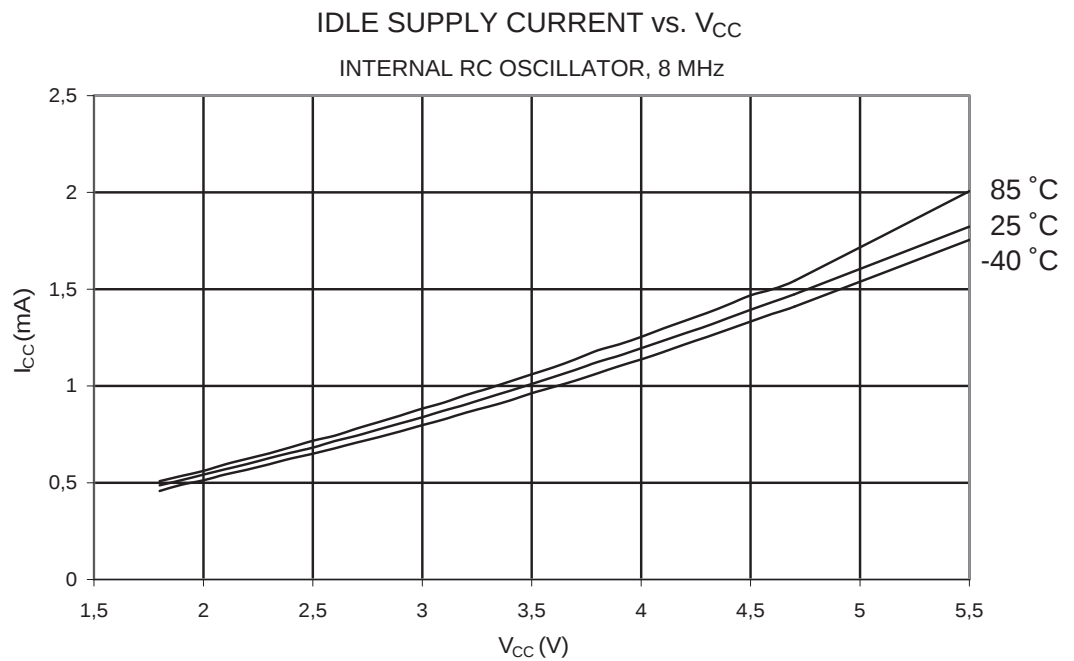
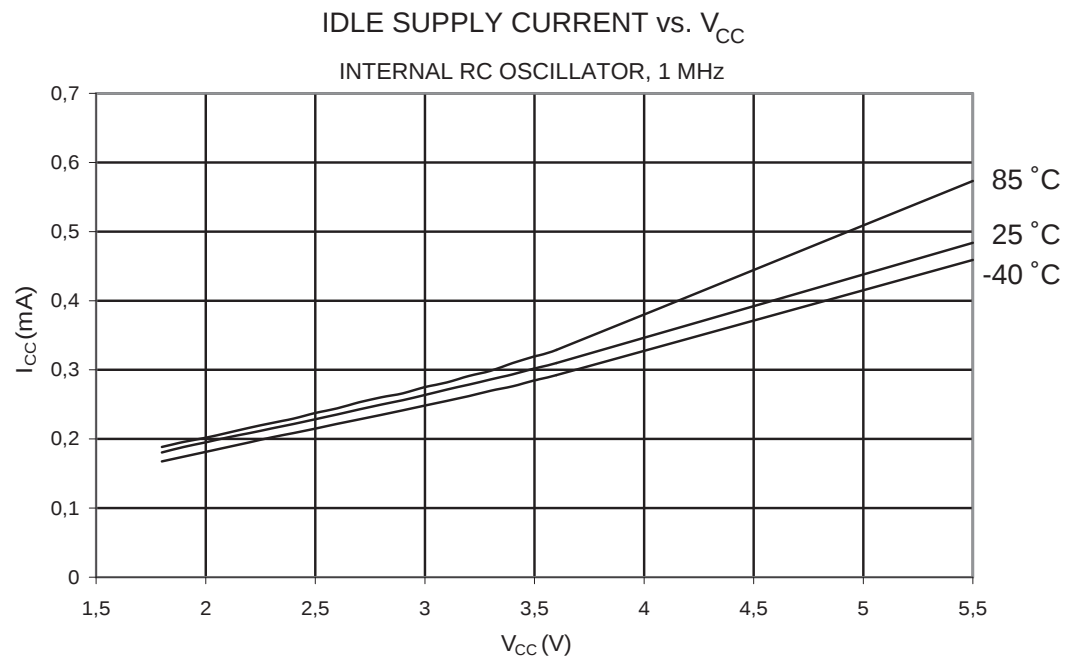
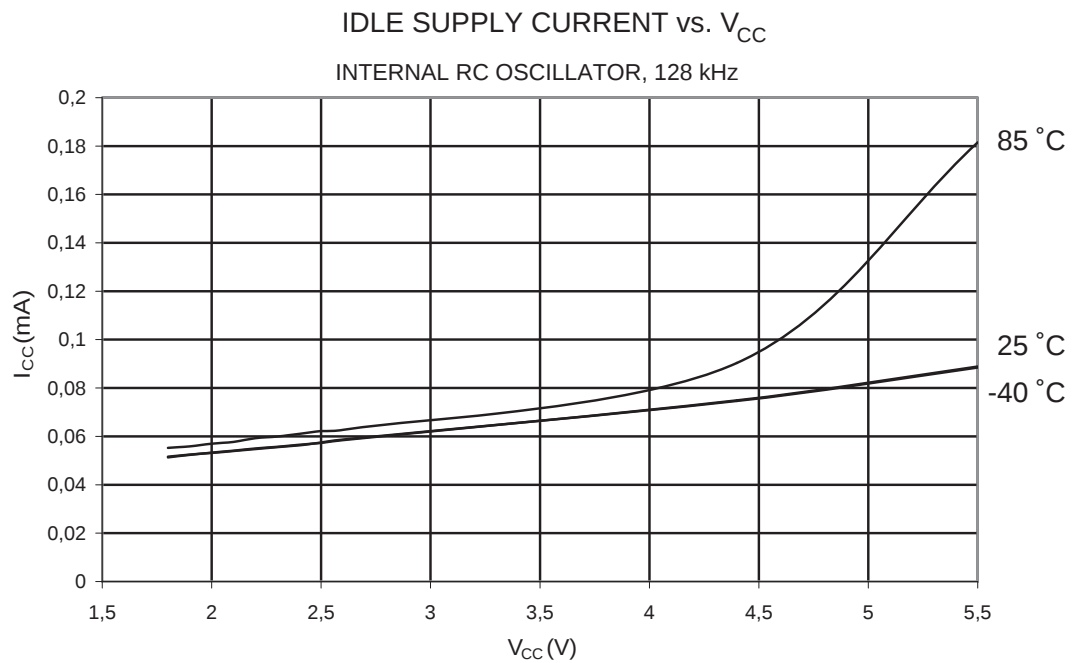
Figure 20-8. Idle Supply Current vs. V_{CC} (Internal RC Oscillator, 8 MHz)**Figure 20-9.** Idle Supply Current vs. V_{CC} (Internal RC Oscillator, 1 MHz)

Figure 20-10. Idle Supply Current vs. V_{CC} (Internal RC Oscillator, 128 kHz)



20.4 Power-down Supply Current

Figure 20-11. Power-down Supply Current vs. V_{CC} (Watchdog Timer Disabled)

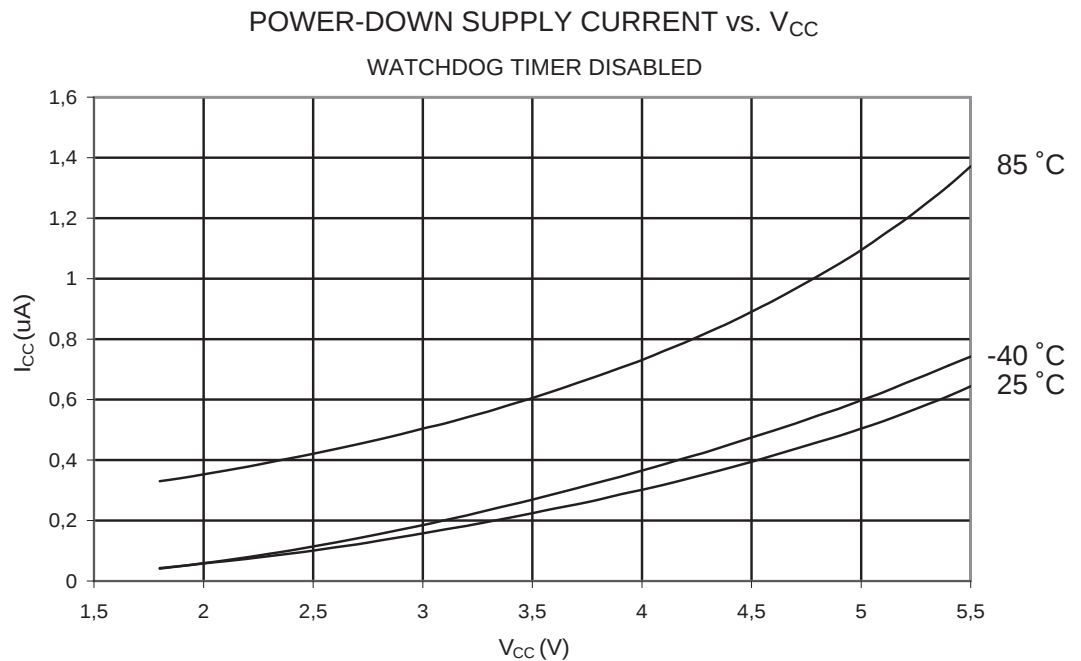
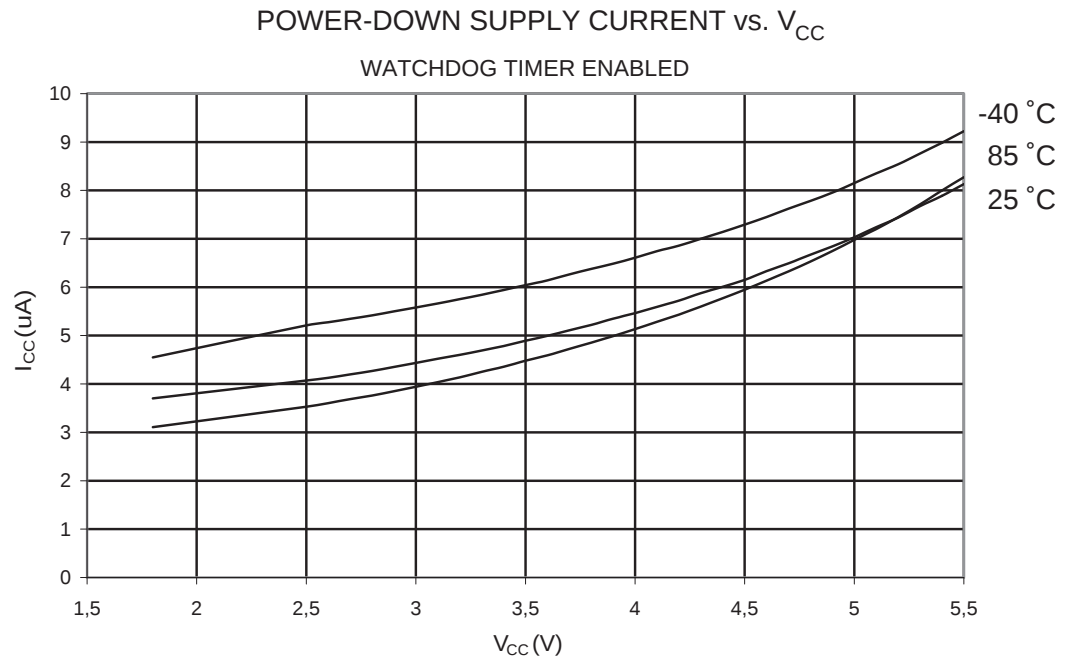


Figure 20-12. Power-down Supply Current vs. V_{CC} (Watchdog Timer Enabled)

20.5 Pin Pull-up

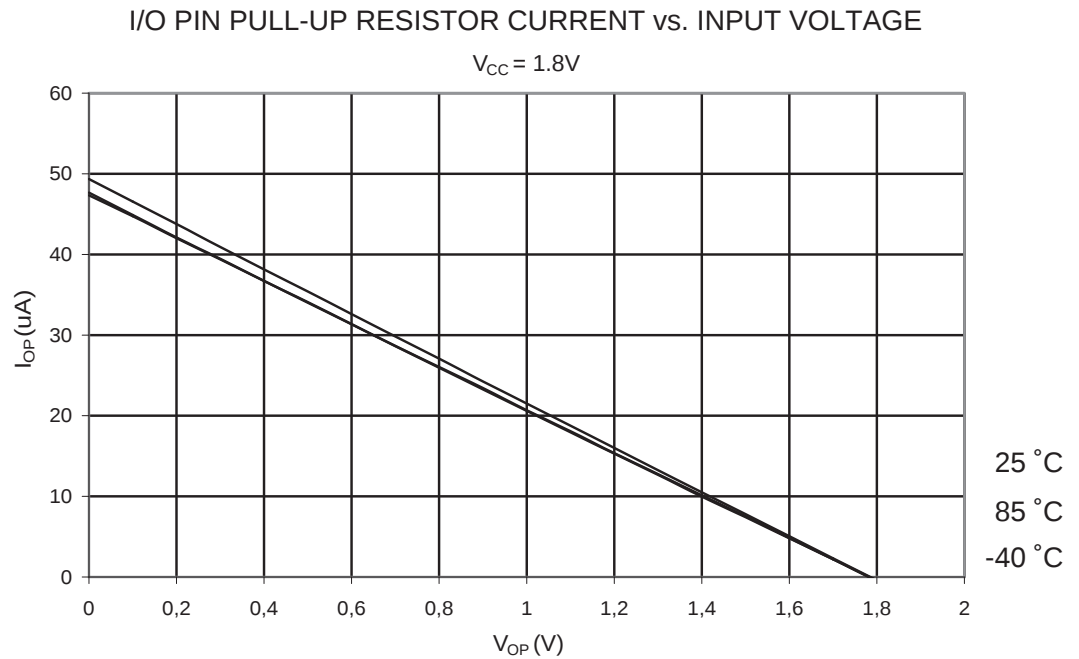
Figure 20-13. I/O Pin pull-up Resistor Current vs. Input Voltage ($V_{CC} = 1.8V$)

Figure 20-14. I/O Pin pull-up Resistor Current vs. Input Voltage ($V_{CC} = 2.7V$)

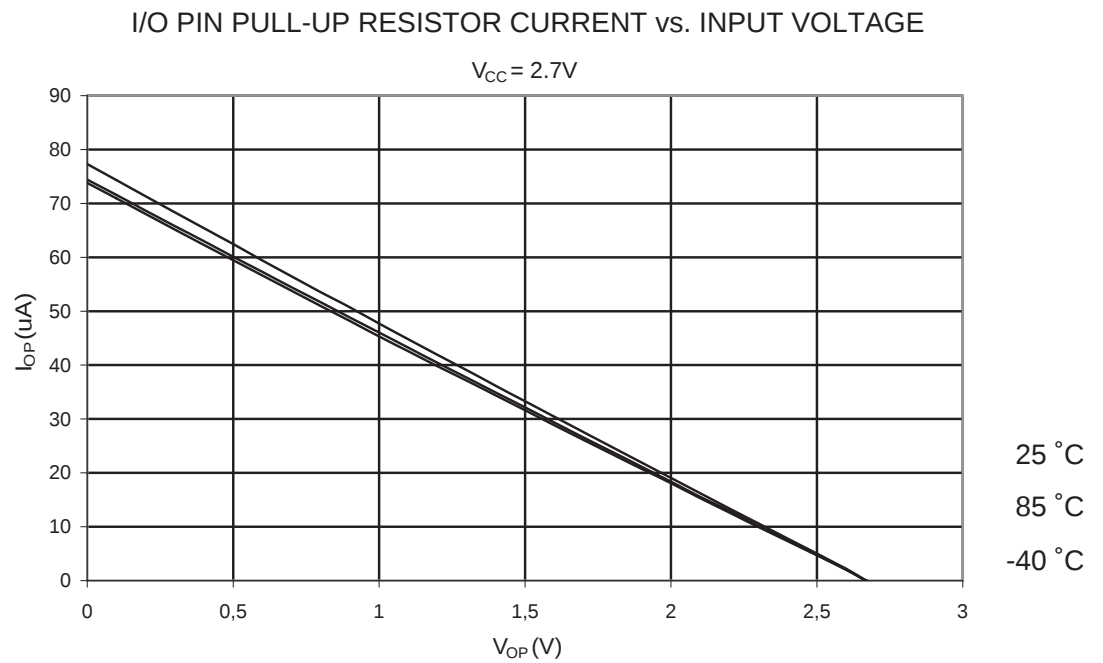


Figure 20-15. I/O Pin pull-up Resistor Current vs. Input Voltage ($V_{CC} = 5V$)

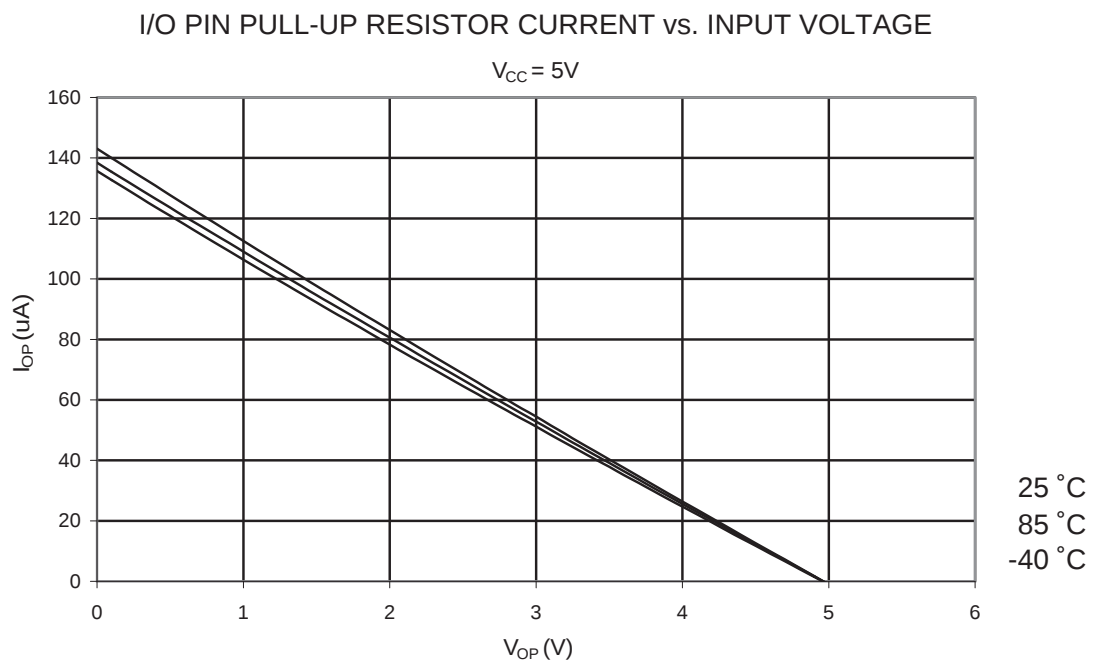


Figure 20-16. Reset Pull-up Resistor Current vs. Reset Pin Voltage ($V_{CC} = 1.8V$)

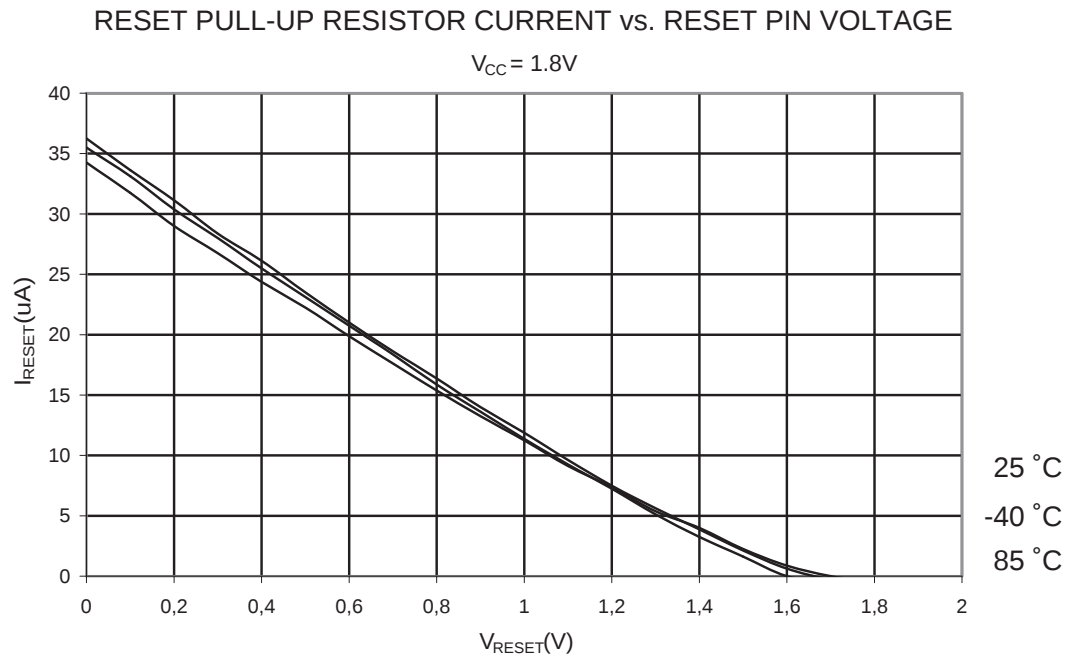


Figure 20-17. Reset Pull-up Resistor Current vs. Reset Pin Voltage ($V_{CC} = 2.7V$)

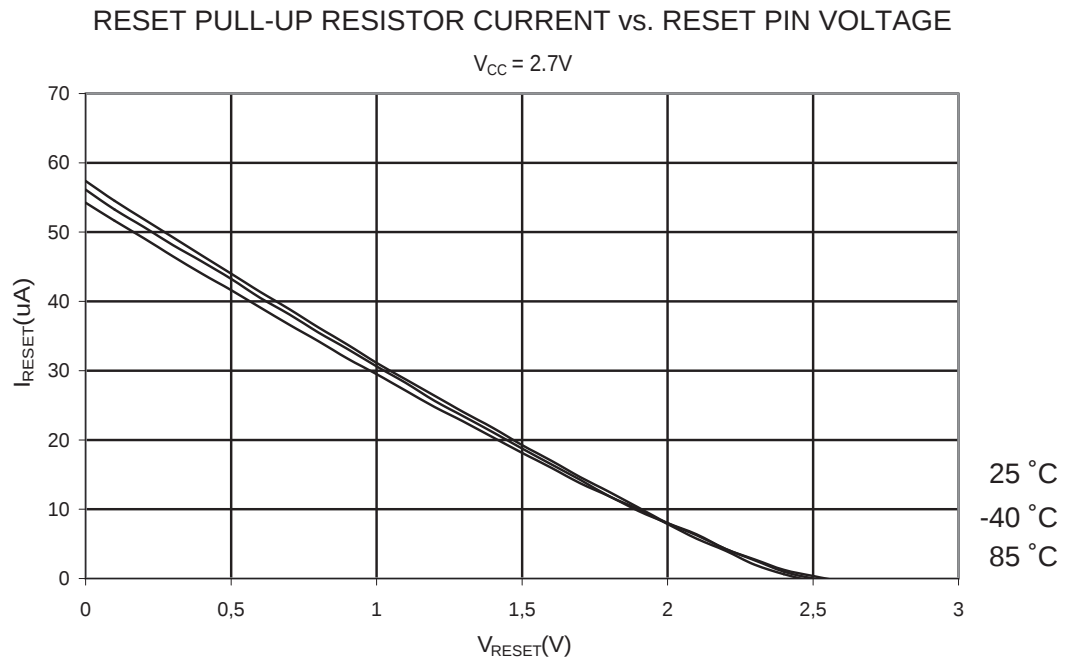
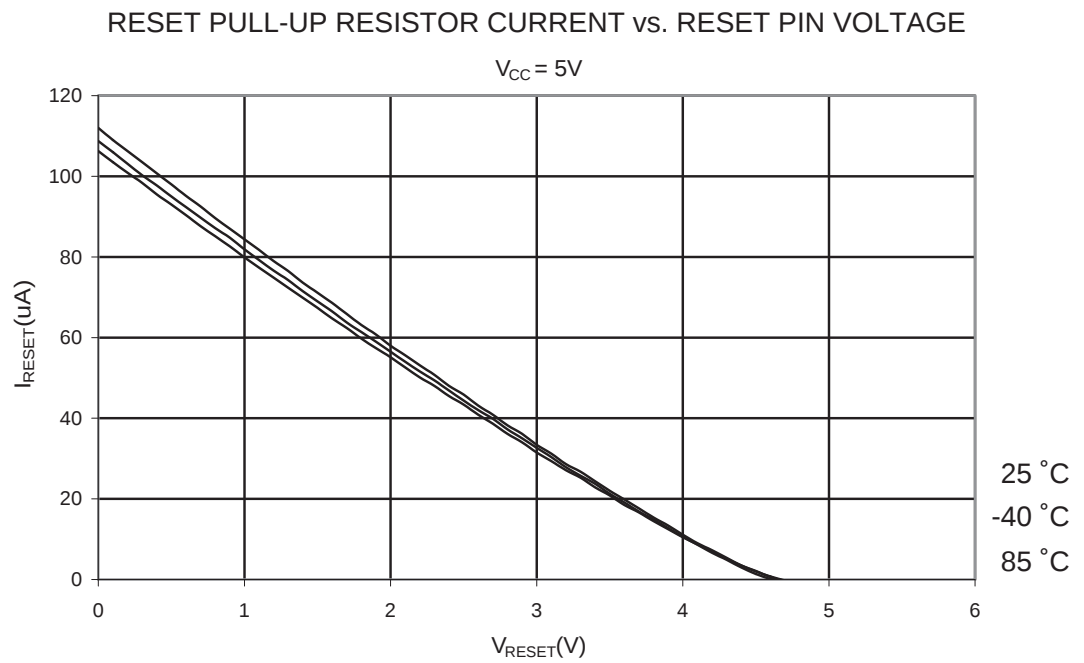


Figure 20-18. Reset Pull-up Resistor Current vs. Reset Pin Voltage ($V_{CC} = 5V$)



20.6 Pin Driver Strength

Figure 20-19. I/O Pin Output Voltage vs. Sink Current ($V_{CC} = 3V$)

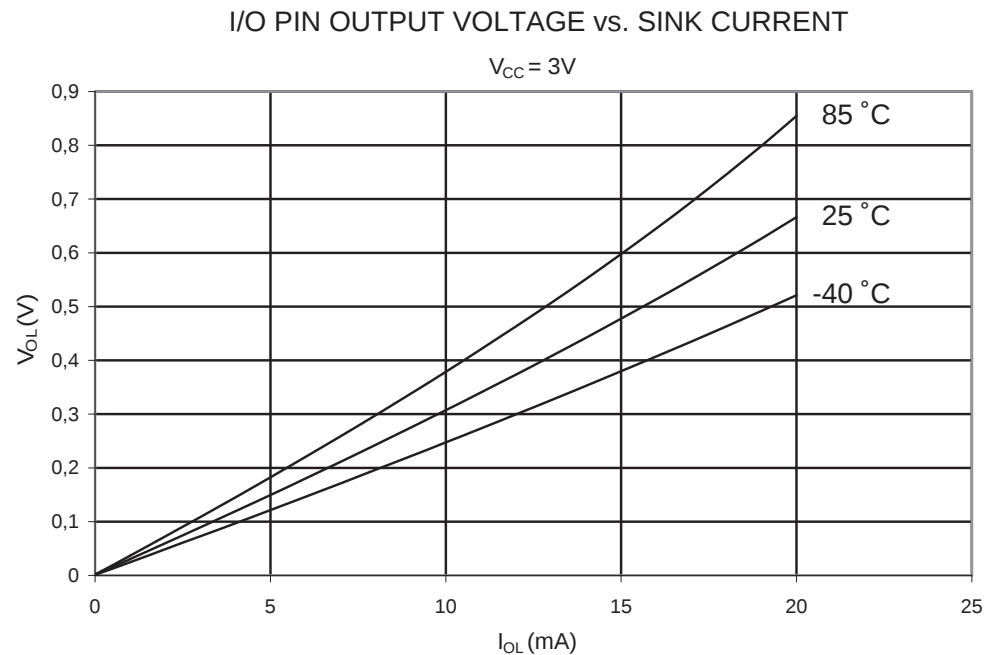


Figure 20-20. I/O Pin Output Voltage vs. Sink Current ($V_{CC} = 5V$)

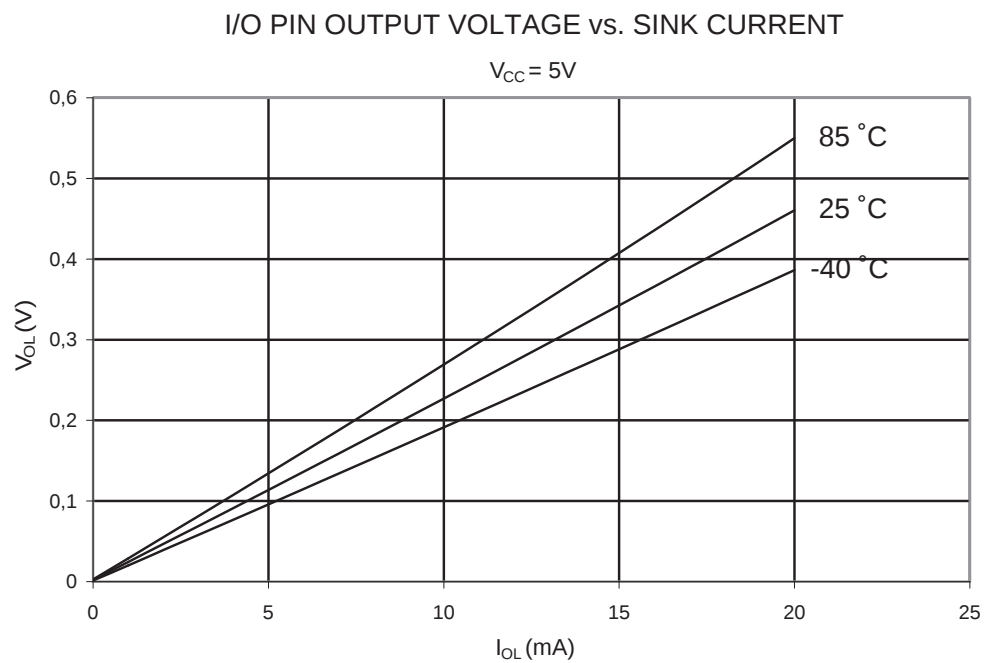


Figure 20-21. I/O Pin Output Voltage vs. Source Current ($V_{CC} = 3V$)

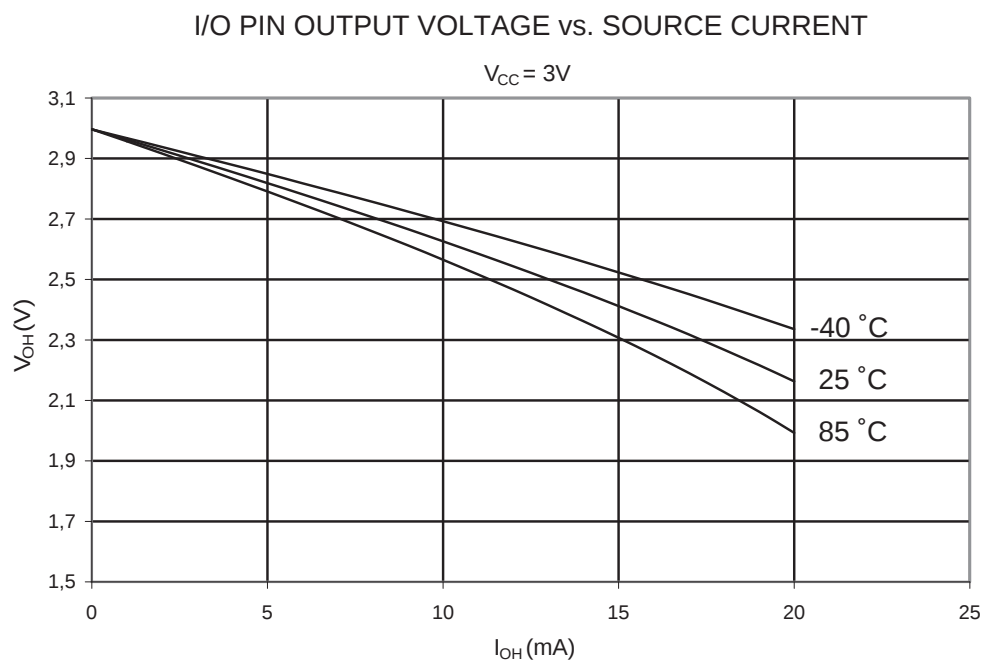


Figure 20-22. I/O Pin Output Voltage vs. Source Current ($V_{CC} = 5V$)

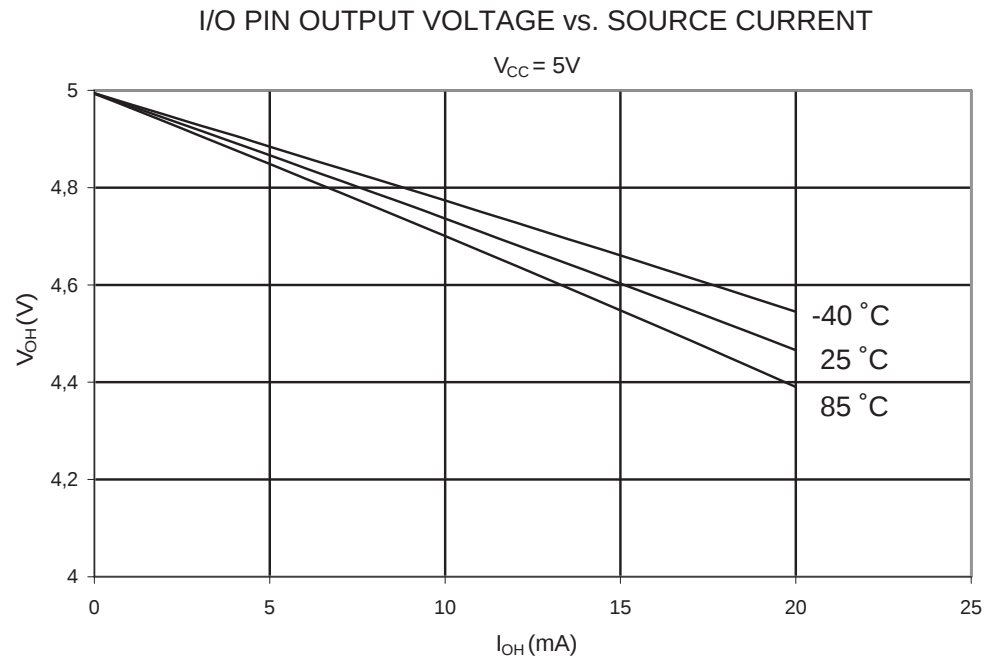


Figure 20-23. Reset Pin Output Voltage vs. Sink Current ($V_{CC} = 3V$)

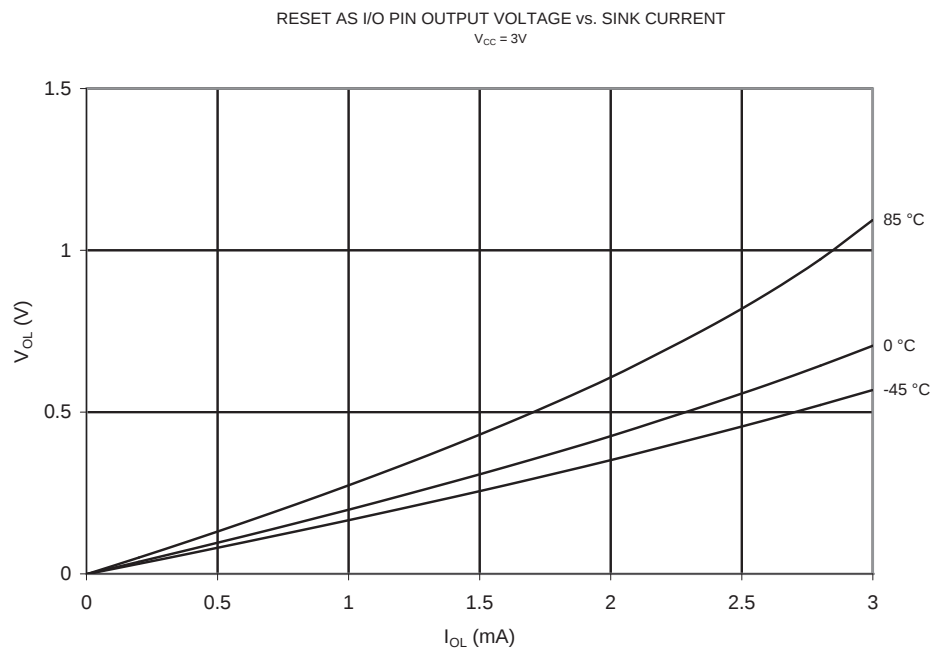


Figure 20-24. Reset Pin Output Voltage vs. Sink Current ($V_{CC} = 5V$)

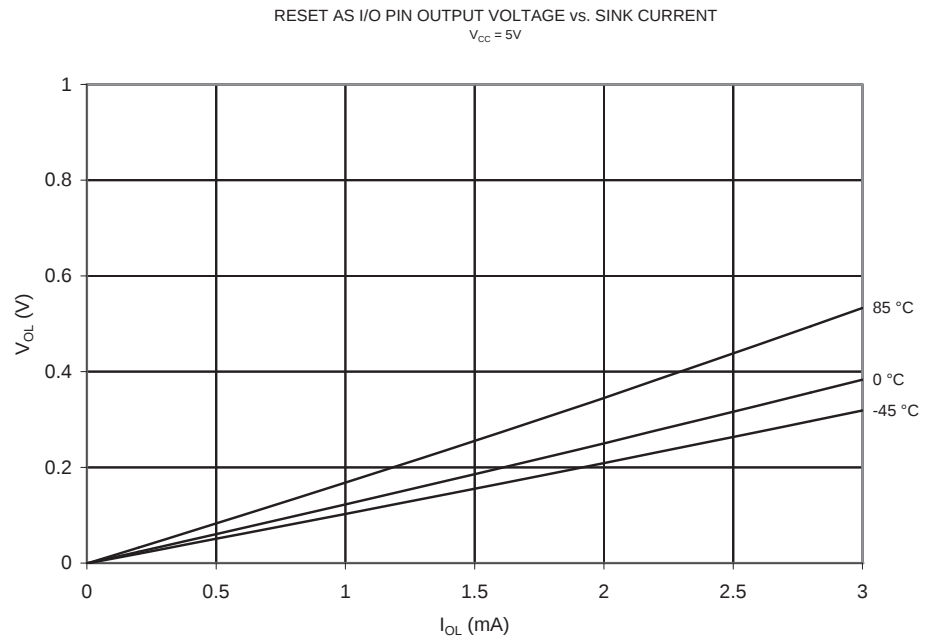


Figure 20-25. Reset Pin Output Voltage vs. Source Current ($V_{CC} = 3V$)

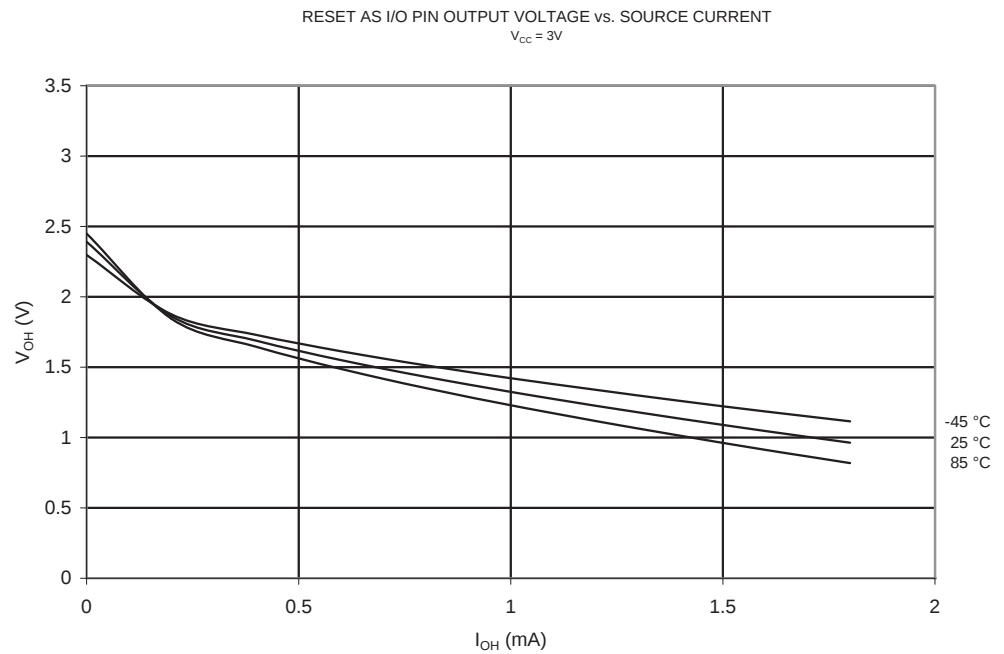
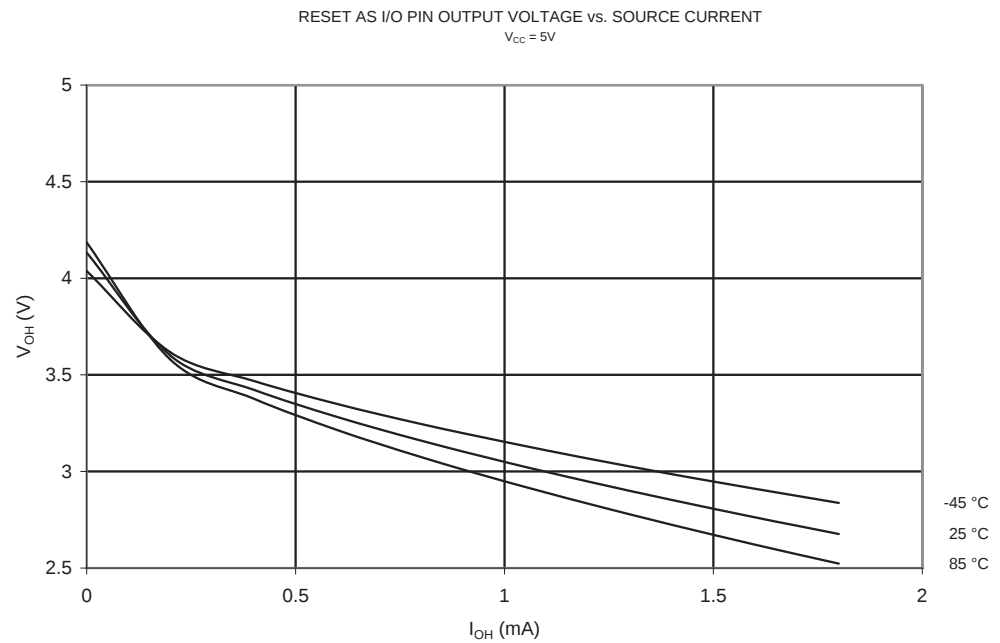


Figure 20-26. Reset Pin Output Voltage vs. Source Current ($V_{CC} = 5V$)



20.7 Pin Threshold and Hysteresis

Figure 20-27. I/O Pin Input Threshold Voltage vs. V_{CC} (V_{IH} , I/O Pin Read as '1')

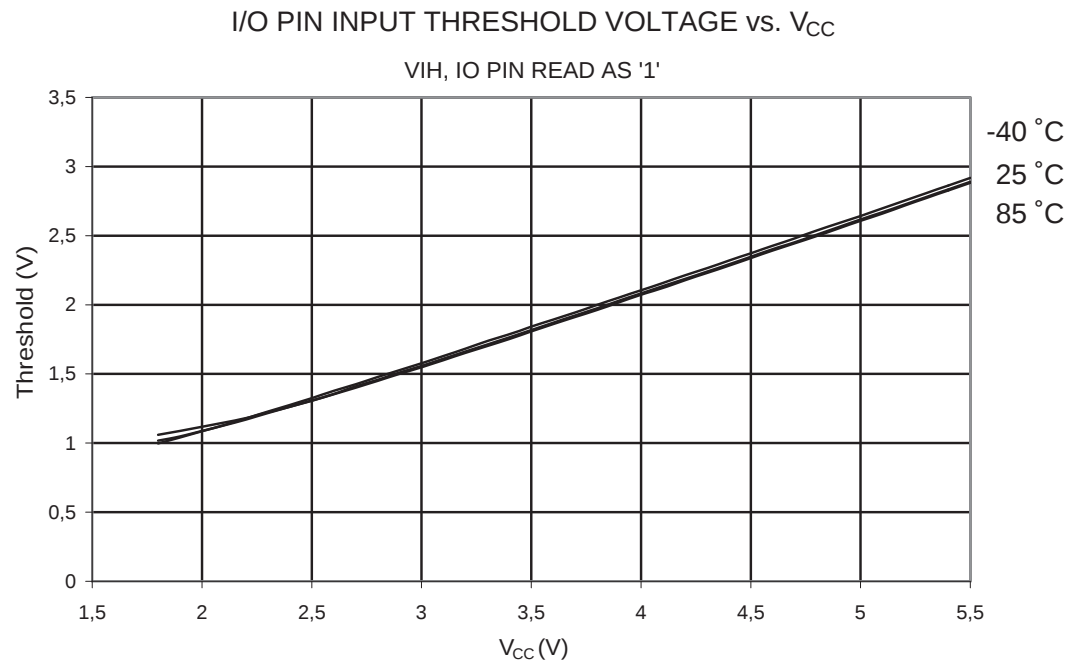


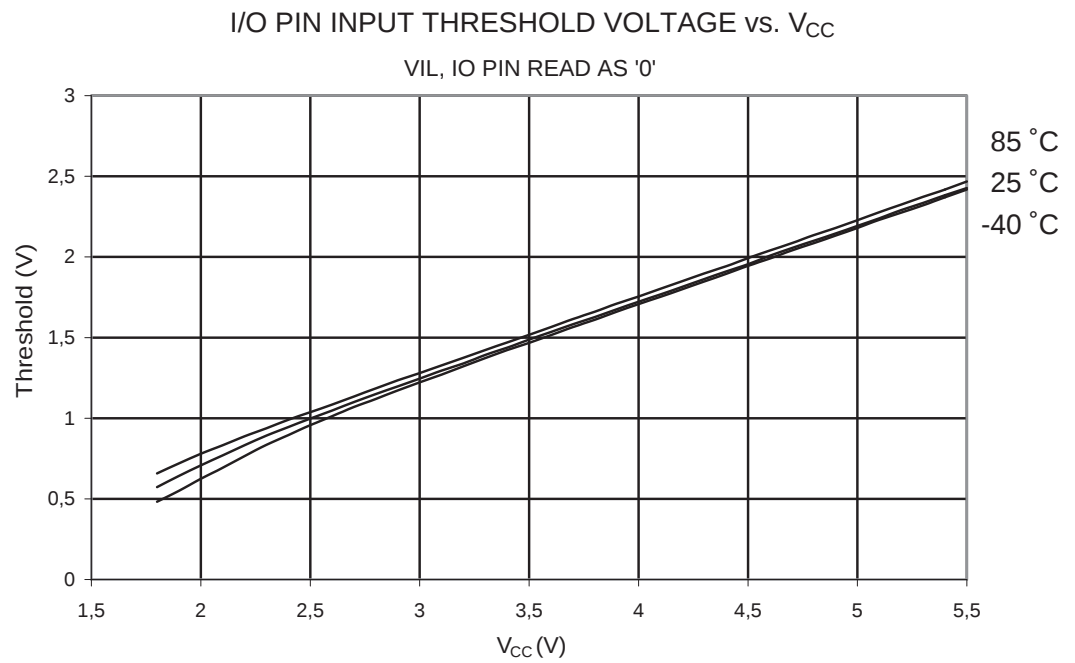
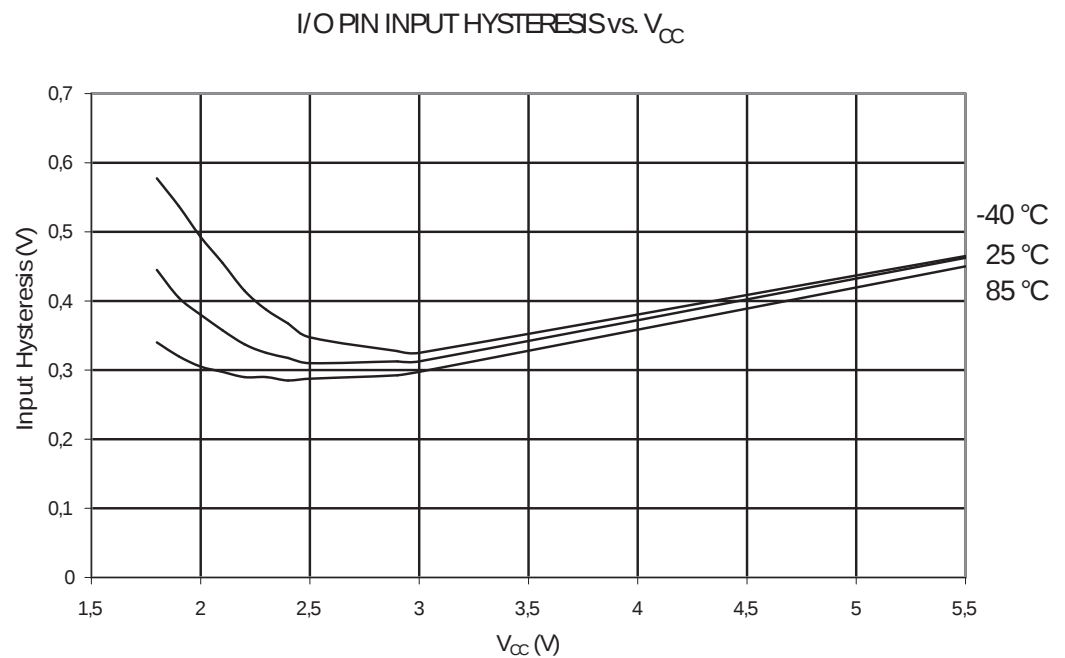
Figure 20-28. I/O Pin Input Threshold Voltage vs. V_{CC} (V_{IL} , I/O Pin Read as '0')**Figure 20-29.** I/O Pin Input Hysteresis vs. V_{CC} 

Figure 20-30. Reset Input Threshold Voltage vs. V_{CC} (V_{IH} , Reset Read as '1')

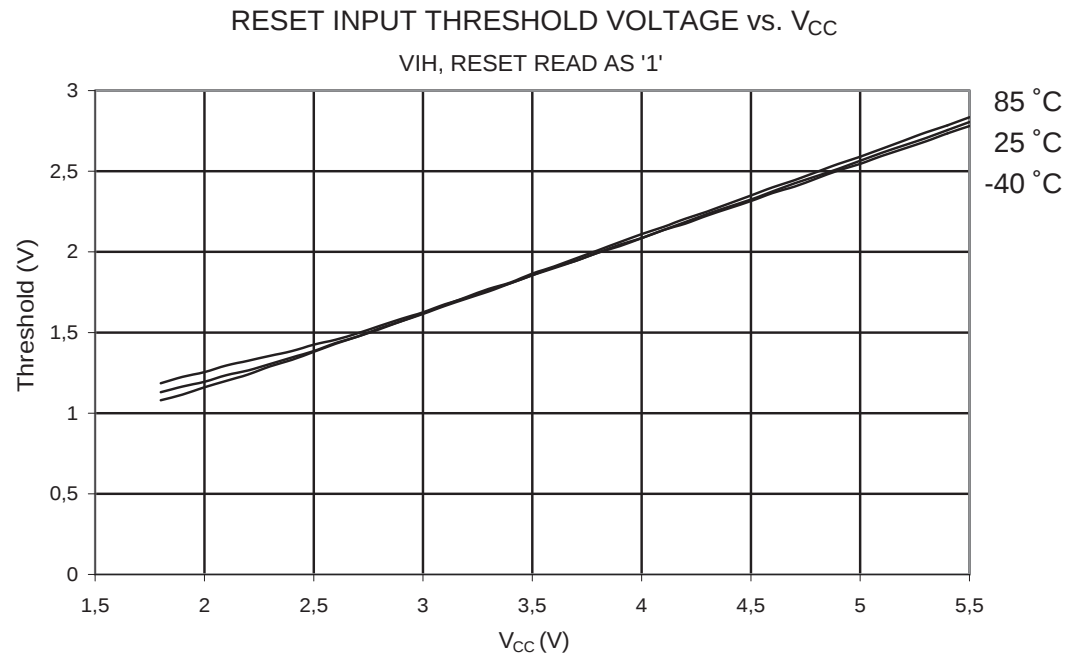


Figure 20-31. Reset Input Threshold Voltage vs. V_{CC} (V_{IL} , Reset Read as '0')

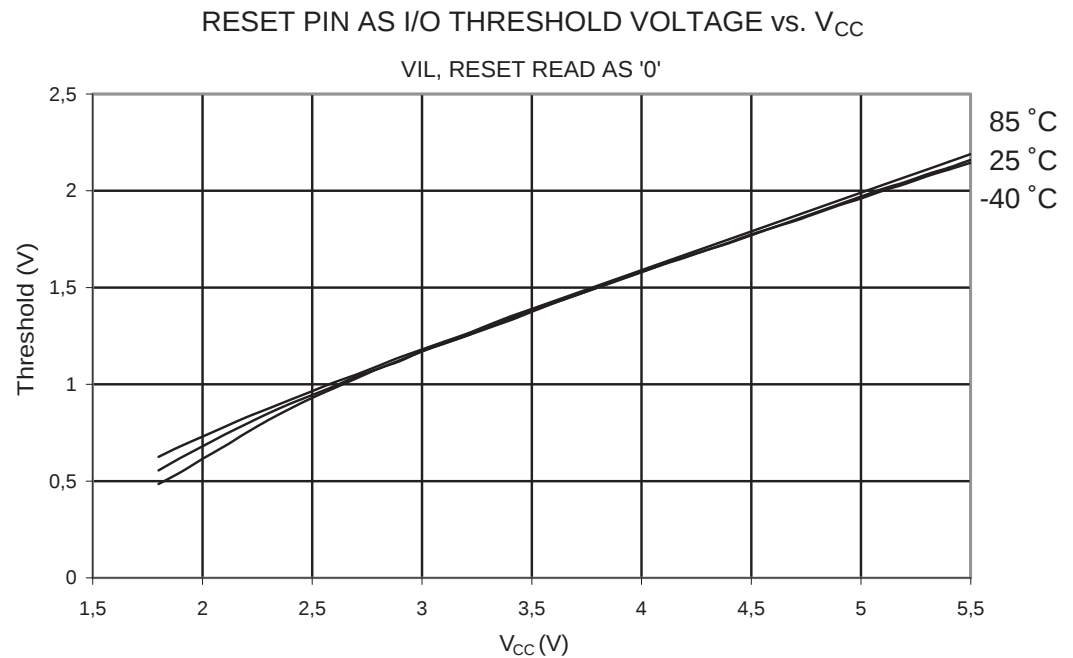
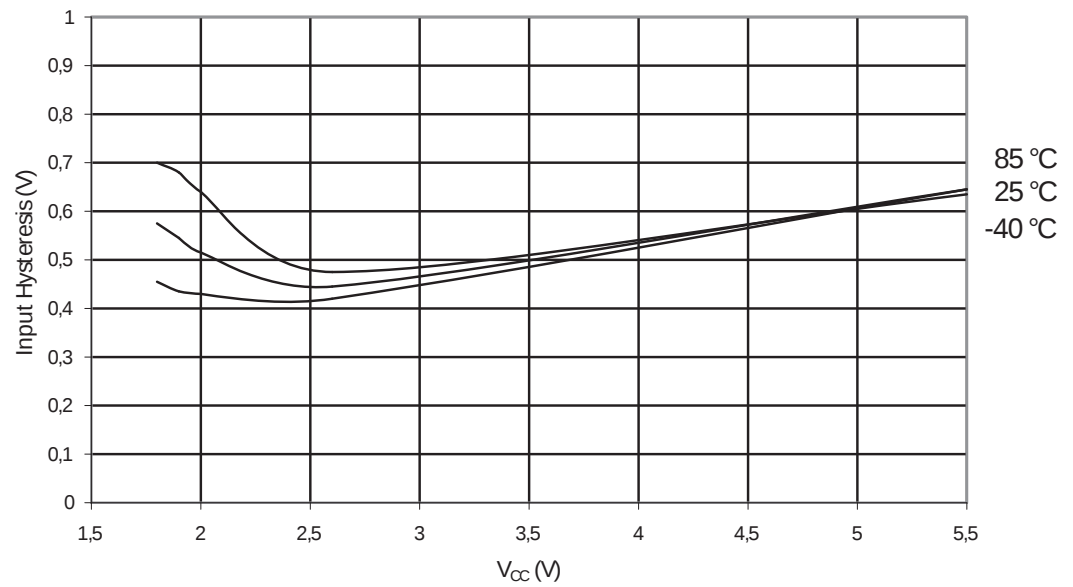


Figure 20-32. Reset Pin input Hysteresis vs. V_{CC} RESET PIN INPUT HYSTERESIS vs. V_{CC} 

20.8 BOD and Bandgap

Figure 20-33. BOD Threshold vs. Temperature (BOD Level is 4.3V)

BOD THRESHOLDS vs. TEMPERATURE

BODLEVEL is 4.3V

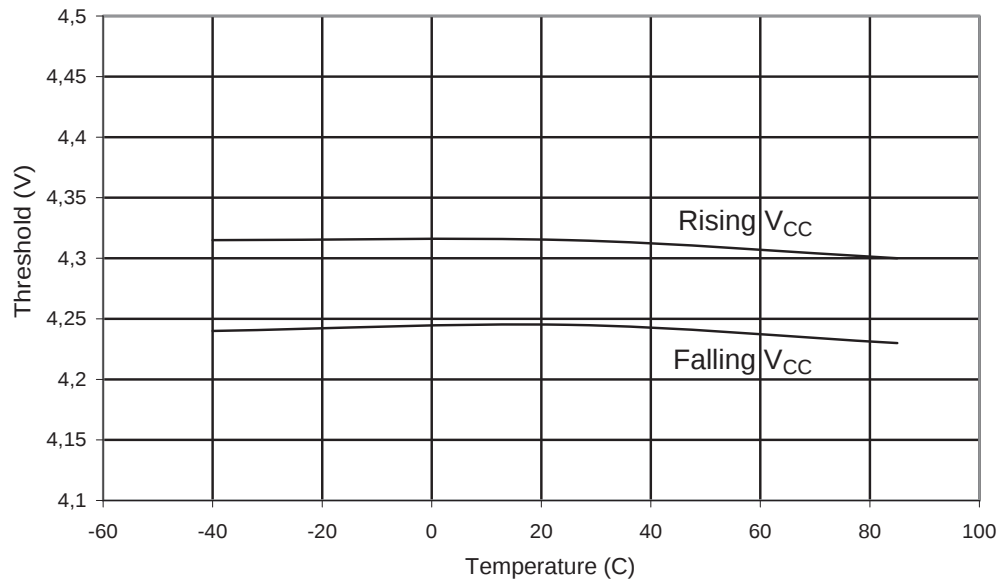


Figure 20-34. BOD Threshold vs. Temperature (BOD Level is 2.7V)

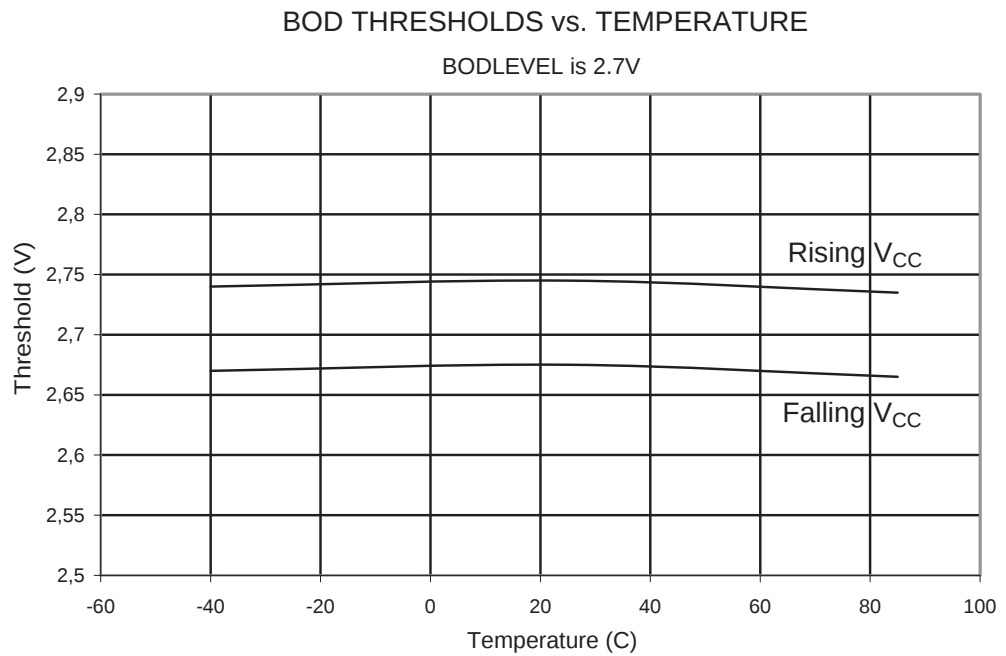


Figure 20-35. BOD Threshold vs. Temperature (BOD Level is 1.8V)

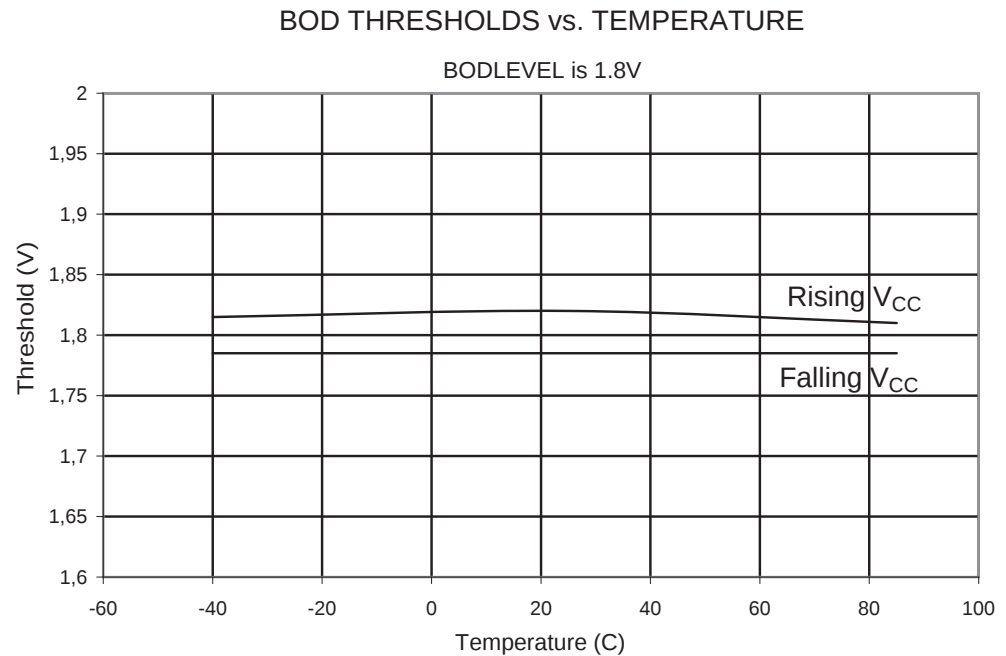
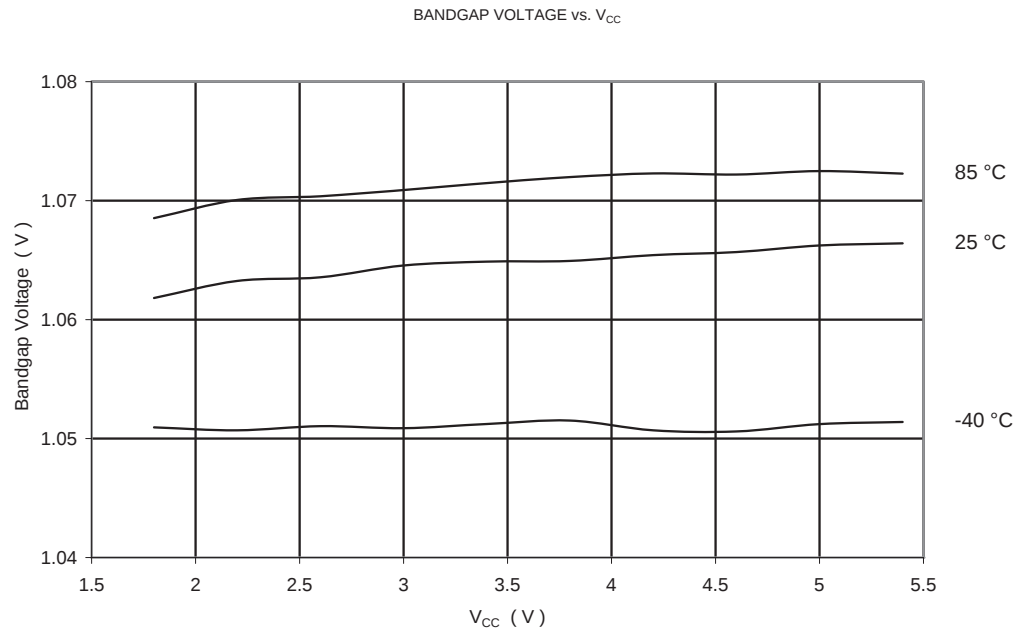


Figure 20-36. Bandgap Voltage vs. Supply Voltage (V_{CC}).

20.9 Internal Oscillator Speed

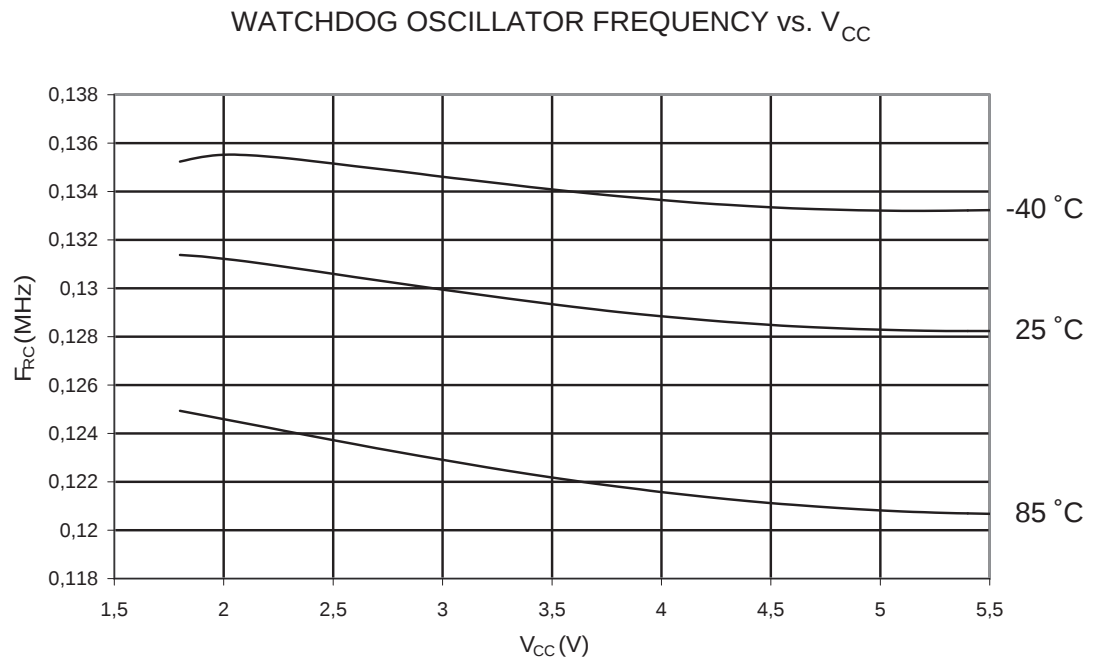
Figure 20-37. Watchdog Oscillator Frequency vs. V_{CC} 

Figure 20-38. Calibrated 8.0 MHz RC Oscillator Frequency vs. V_{CC}

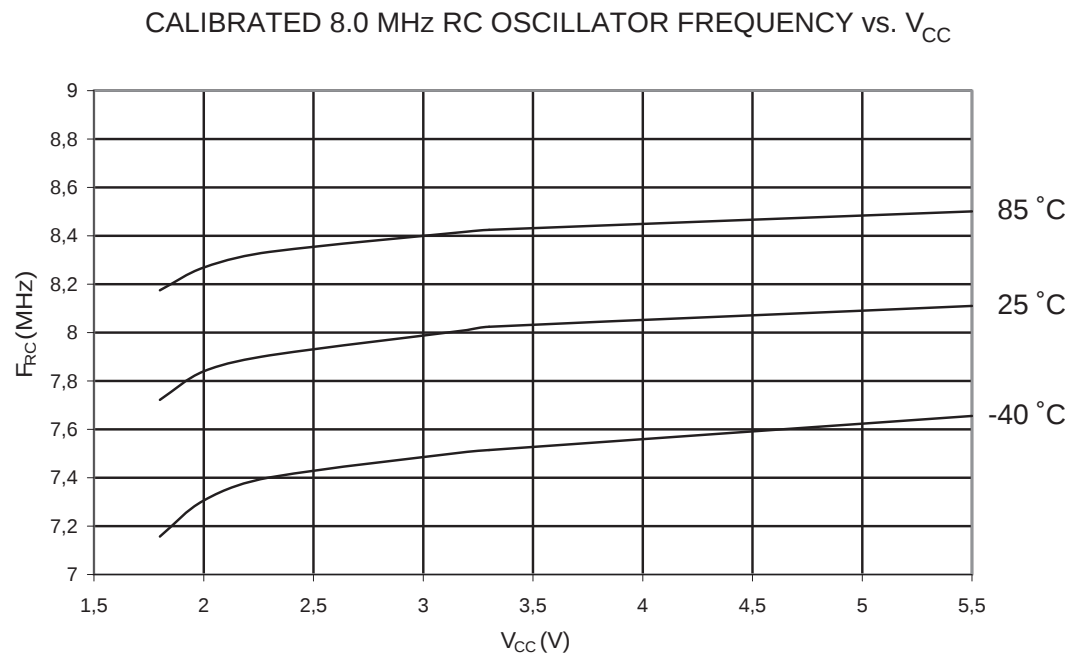


Figure 20-39. Calibrated 8.0 MHz RC Oscillator Frequency vs. Temperature

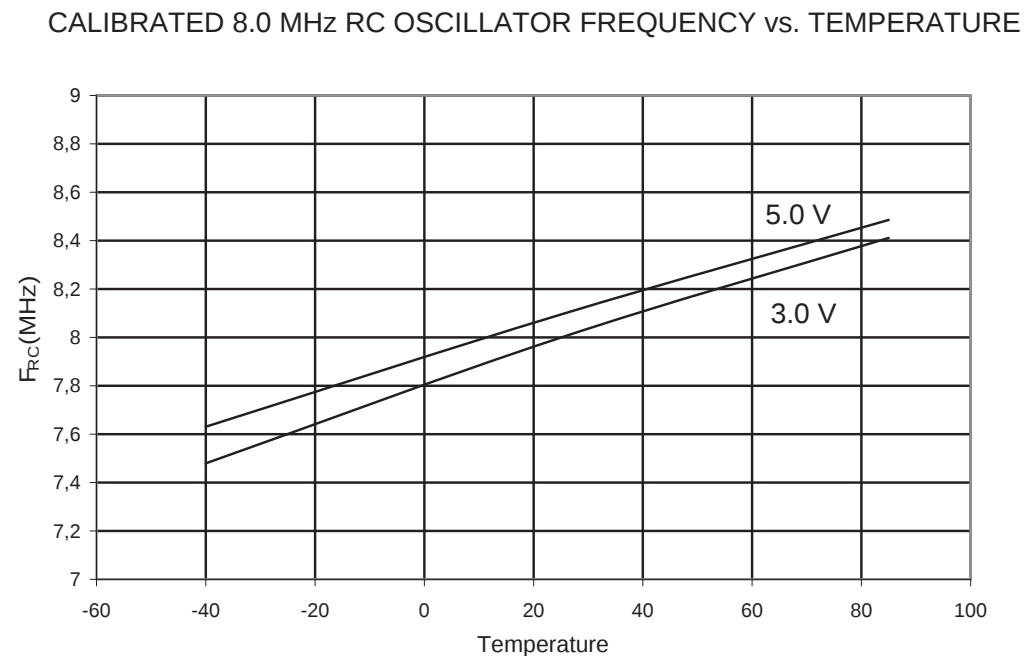
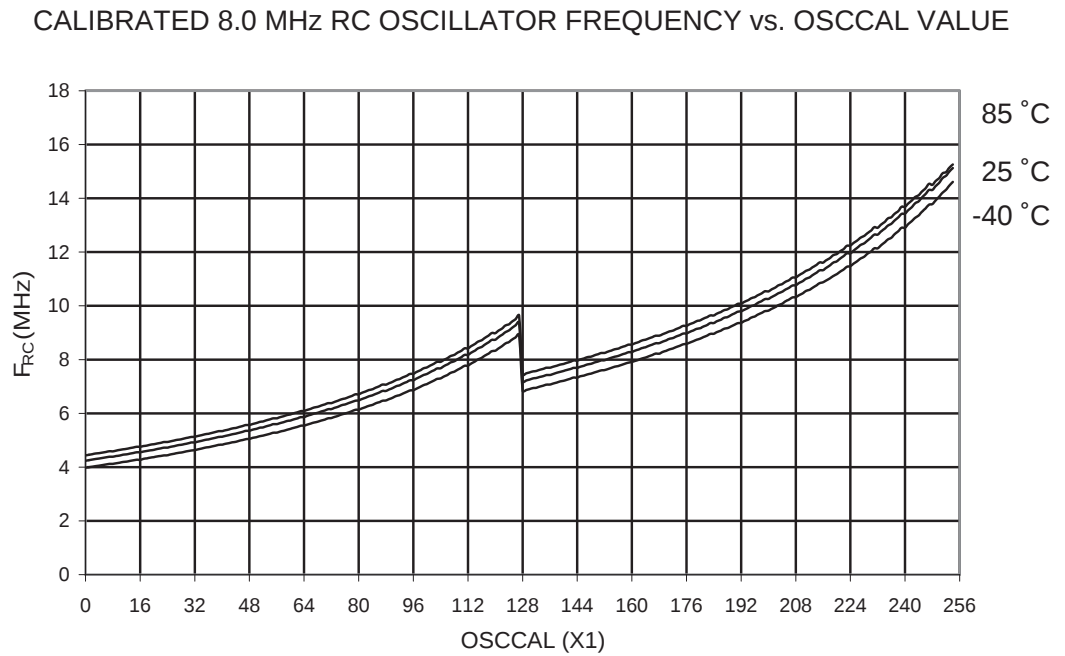


Figure 20-40. Calibrated 8.0 MHz RC Oscillator Frequency vs. OSCCAL Value

20.10 Current Consumption of Peripheral Units

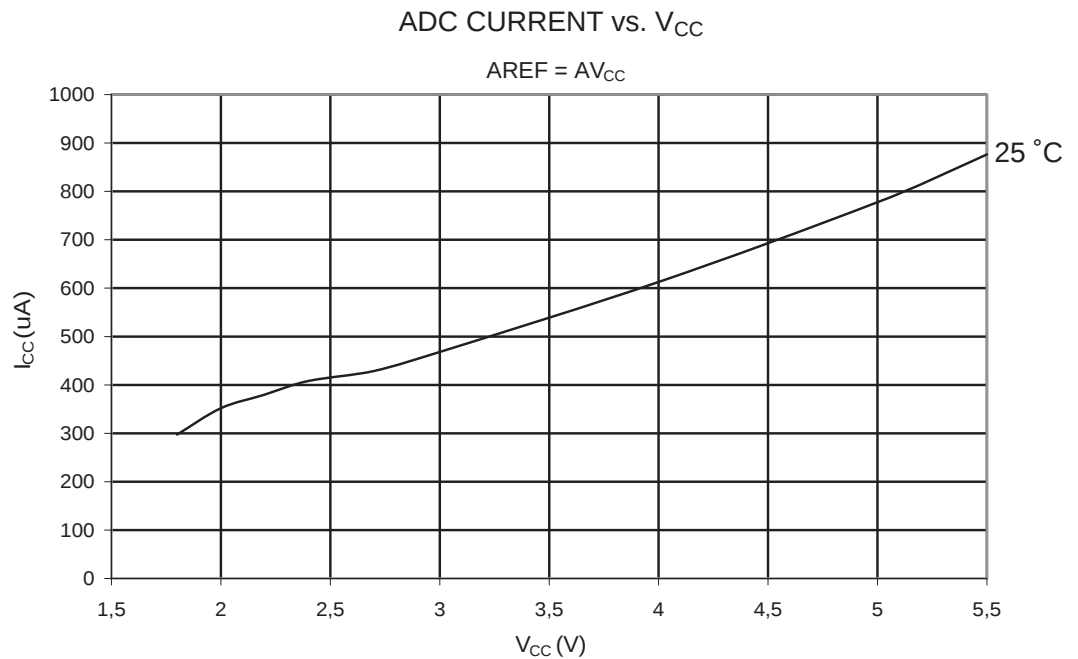
Figure 20-41. ADC Current vs. V_{CC} (AREF = AV_{CC})

Figure 20-42. AREF External Reference Current vs. V_{CC}

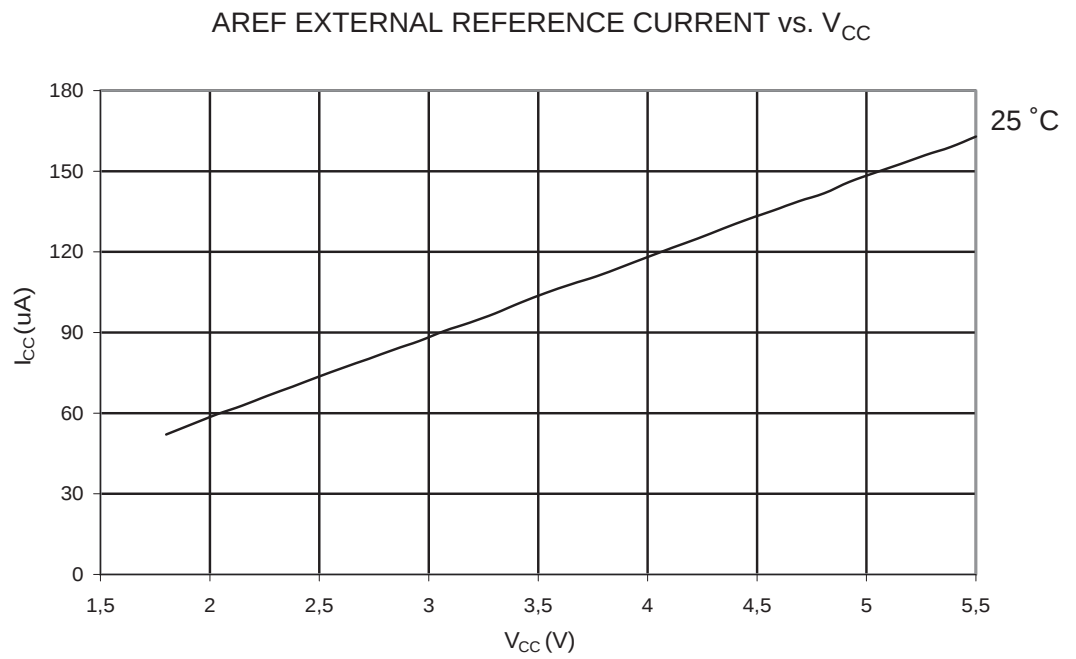


Figure 20-43. Analog Comparator vs. V_{CC}

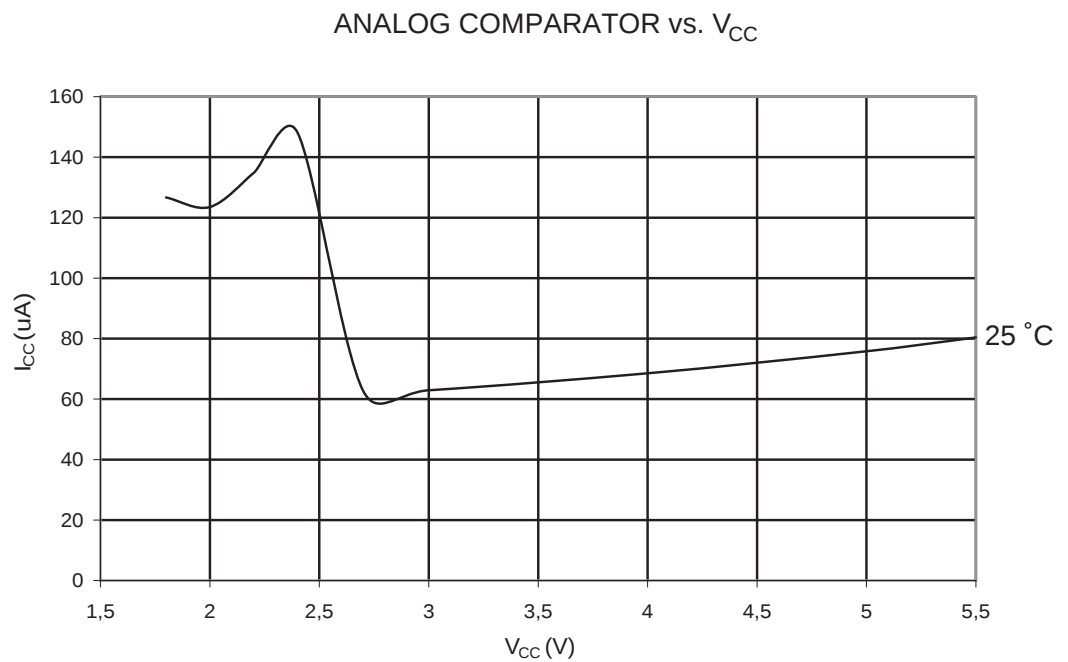


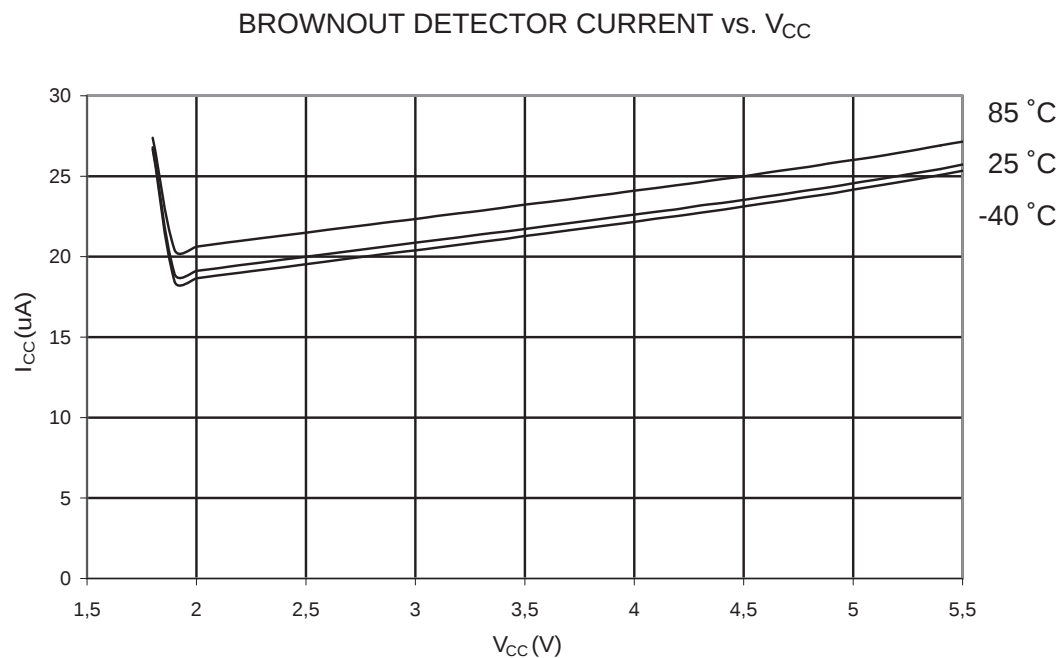
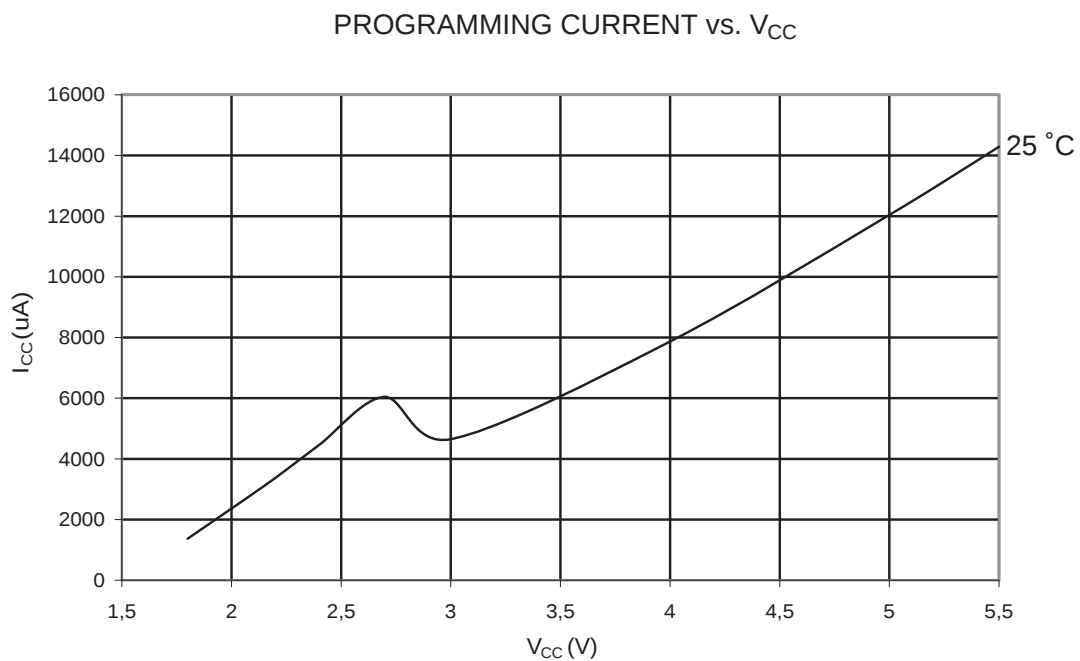
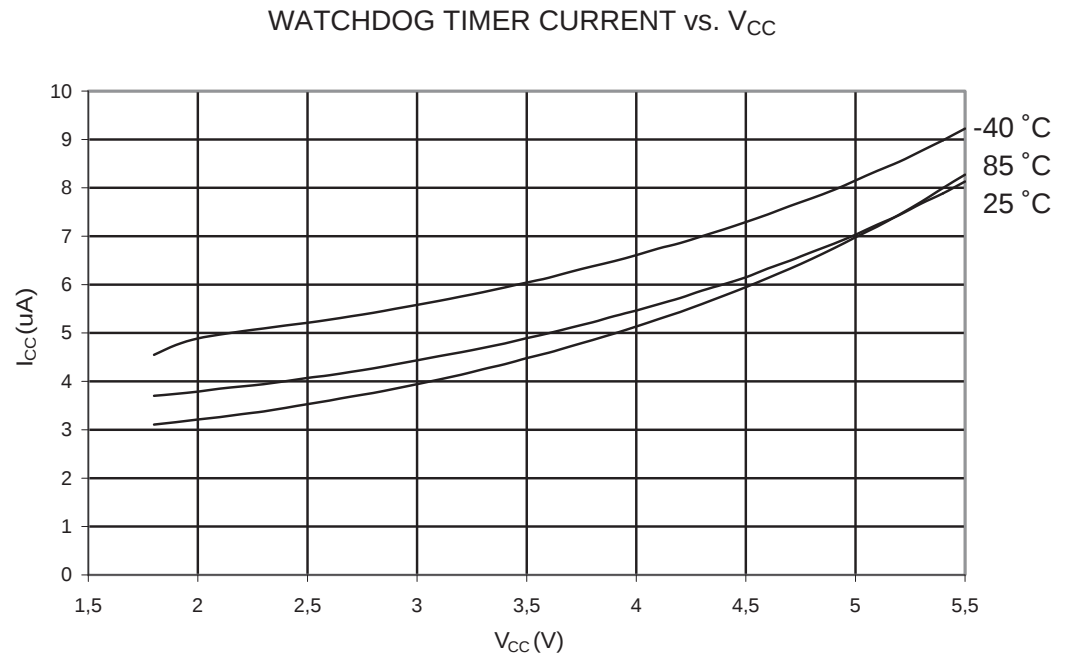
Figure 20-44. Brownout Detector Current vs. V_{CC} **Figure 20-45.** Programming Current vs. V_{CC} 

Figure 20-46. Watchdog Timer Current vs. V_{CC}



20.11 Current Consumption in Reset and Reset Pulsewidth

Figure 20-47. Reset Supply Current vs. Low Frequency (0.1 - 1.0 MHz, Excluding Current Through the Reset Pull-up)

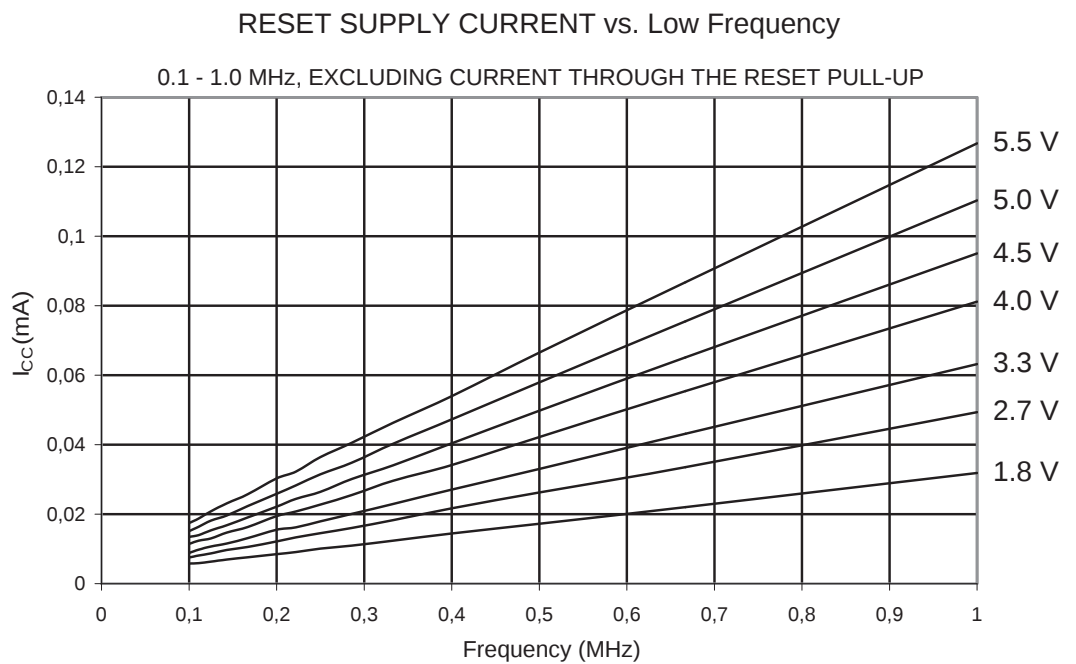


Figure 20-48. Reset Supply Current vs. Frequency (1 - 20 MHz, Excluding Current Through the Reset Pull-up)

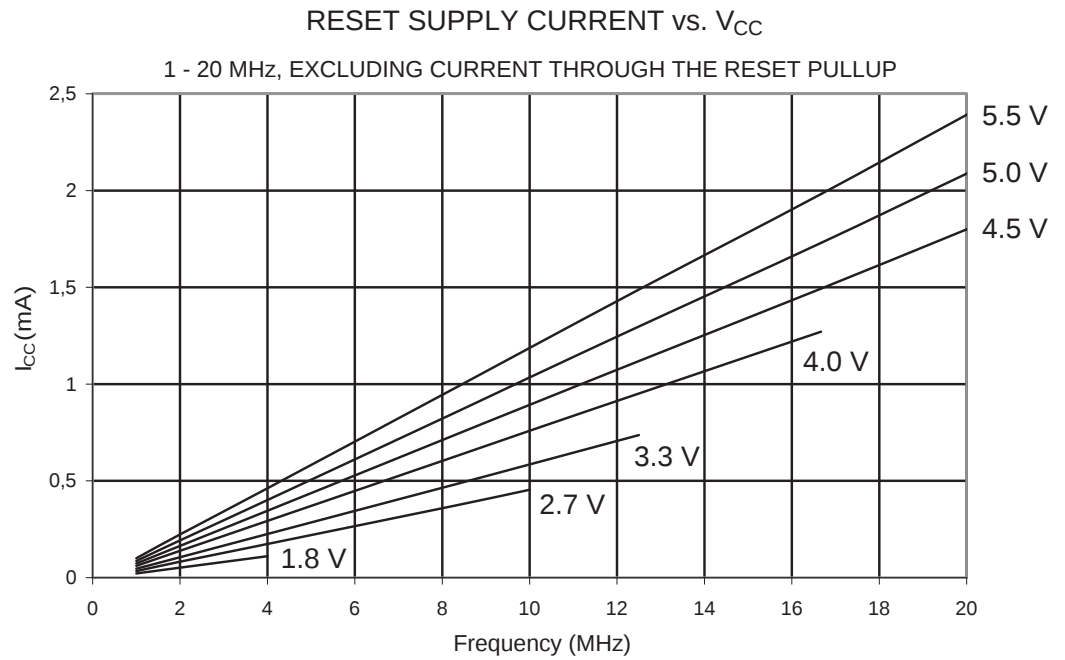
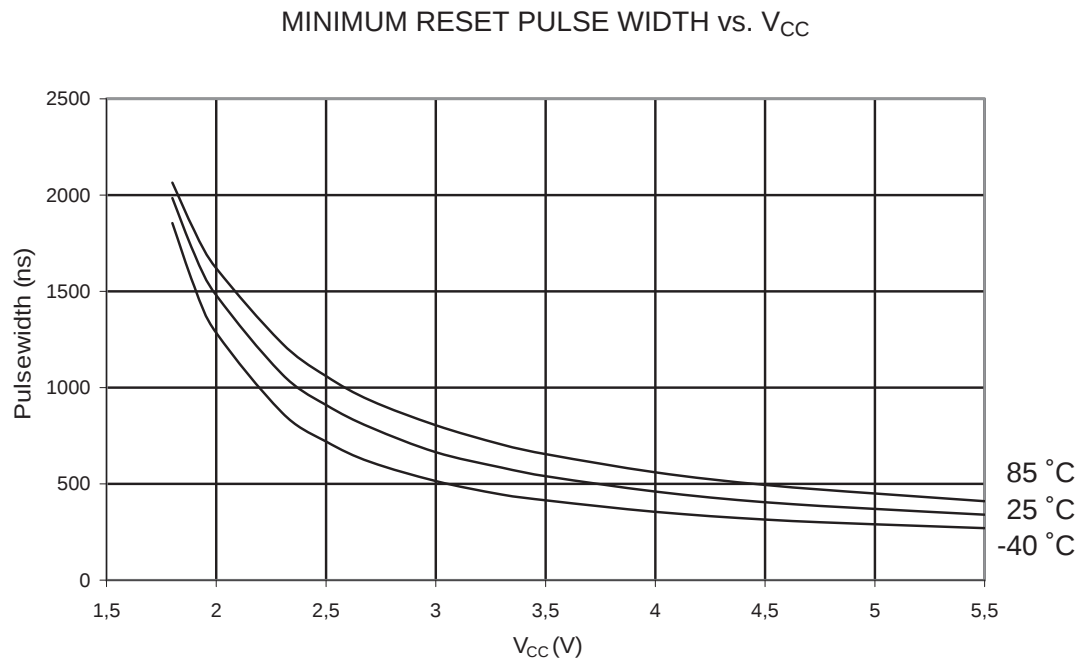


Figure 20-49. Minimum Reset Pulse Width vs. V_{CC}



21. Register Summary

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Page
0x3F (0x5F)	SREG	I	T	H	S	V	N	Z	C	page 8
0x3E (0x5E)	SPH	–	–	–	–	–	SP10	SP9	SP8	page 11
0x3D (0x5D)	SPL	SP7	SP6	SP5	SP4	SP3	SP2	SP1	SP0	page 11
0x3C (0x5C)	Reserved	–								
0x3B (0x5B)	GIMSK	INT1	INT0	PCIE1	PCIE0	–	–	–	–	page 52
0x3A (0x5A)	GIFR	INTF1	INTF0	PCIF	–	–	–	–	–	page 53
0x39 (0x59)	TIMSK	OCIE1D	OCIE1A	OCIE1B	OCIE0A	OCIE0B	TOIE1	TOIE0	TICIE0	page 86 , page 123
0x38 (0x58)	TIFR	OCF1D	OCF1A	OCF1B	OCF0A	OCF0B	TOV1	TOV0	ICF0	page 87 , page 123
0x37 (0x57)	SPMCSR	–	–	–	CTPB	RFLB	PGWRT	PGERS	SPMEN	page 169
0x36 (0x56)	PRR	–	–	–	–	PRTIM1	PRTIM0	PRUSI	PRADC	page 37
0x35 (0x55)	MCUCR	–	PUD	SE	SM1	SM0	–	ISC01	ISC00	page 39 , page 69 , page 52
0x34 (0x54)	MCUSR	–	–	–	–	WDRF	BORF	EXTRF	PORF	page 47 , page 85
0x33 (0x53)	TCCR0B	–	–	–	TSM	PSR0	CS02	CS01	CS00	
0x32 (0x52)	TCNT0L	Timer/Counter0 Counter Register Low Byte								page 85
0x31 (0x51)	OSCCAL	Oscillator Calibration Register								page 32
0x30 (0x50)	TCCR1A	COM1A1	COM1A0	COM1B1	COM1B0	FOC1A	FOC1B	PWM1A	PWM1B	page 112
0x2F (0x4F)	TCCR1B	PWM1X	PSR1	DTPS11	DTPS10	CS13	CS12	CS11	CS10	page 169
0x2E (0x4E)	TCNT1	Timer/Counter1 Counter Register								page 121
0x2D (0x4D)	OCR1A	Timer/Counter1 Output Compare Register A								page 121
0x2C (0x4C)	OCR1B	Timer/Counter1 Output Compare Register B								page 122
0x2B (0x4B)	OCR1C	Timer/Counter1 Output Compare Register C								page 122
0x2A (0x4A)	OCR1D	Timer/Counter1 Output Compare Register D								page 122
0x29 (0x49)	PLLCR	LSM	–	–	–	–	PCKE	PLLE	PLOCK	page 120
0x28 (0x48)	CLKPR	CLKPCE	–	–	–	CLKPS3	CLKPS2	CLKPS1	CLKPS0	page 32
0x27 (0x47)	TCCR1C	COM1A1S	COM1A0S	COM1B1S	COM1B0S	COM1D1	COM1D0	FOC1D	PWM1D	page 117
0x26 (0x46)	TCCR1D	FP1E1	FPEN1	FPNC1	FPES1	FPAC1	FPF1	WGM11	WGM10	page 118
0x25 (0x45)	TC1H	–	–	–	–	–	–	TC19	TC18	page 121
0x24 (0x44)	DT1	DT1H3	DT1H2	DT1H1	DT1H0	DT1L3	DT1L2	DT1L1	DT1L0	page 124
0x23 (0x43)	PCMSK0	PCINT7	PCINT6	PCINT5	PCINT4	PCINT3	PCINT2	PCINT1	PCINT0	page 54
0x22 (0x42)	PCMSK1	PCINT15	PCINT14	PCINT13	PCINT12	PCINT11	PCINT10	PCINT9	PCINT8	page 54
0x21 (0x41)	WDTCSR	WDIF	WDIE	WDP3	WDCE	WDE	WDP2	WDP1	WDP0	page 47
0x20 (0x40)	DWDR	DWDR[7:0]								page 37
0x1F (0x3F)	EEARH	–	–	–	–	–	–	–	EEAR8	page 20
0x1E (0x3E)	EEARL	EEAR7	EEAR6	EEAR5	EEAR4	EEAR3	EEAR2	EEAR1	EEAR0	page 21
0x1D (0x3D)	EEDR	EEPROM Data Register								page 21
0x1C (0x3C)	EECR	–	–	EEDM1	EEDM0	EERIE	EEMPE	EEPE	EERE	page 21
0x1B (0x3B)	PORTA	PORTA7	PORTA6	PORTA5	PORTA4	PORTA3	PORTA2	PORTA1	PORTA0	page 69
0x1A (0x3A)	DDRA	DDA7	DDA6	DDA5	DDA4	DDA3	DDA2	DDA1	DDA0	page 69
0x19 (0x39)	PINA	PINA7	PINA6	PINA5	PINA4	PINA3	PINA2	PINA1	PINA0	page 70
0x18 (0x38)	PORTB	PORTB7	PORTB6	PORTB5	PORTB4	PORTB3	PORTB2	PORTB1	PORTB0	page 70
0x17 (0x37)	DDRB	DDB7	DDB6	DDB5	DDB4	DDB3	DDB2	DDB1	DDB0	page 70
0x16 (0x36)	PINB	PINB7	PINB6	PINB5	PINB4	PINB3	PINB2	PINB1	PINB0	page 70
0x15 (0x35)	TCCR0A	TCW0	ICEN0	ICNC0	ICES0	ACIC0	–	–	CTC0	page 84
0x14 (0x34)	TCNT0H	Timer/Counter0 Counter Register High Byte								page 86
0x13 (0x33)	OCR0A	Timer/Counter0 Output Compare Register A								page 86
0x12 (0x32)	OCR0B	Timer/Counter0 Output Compare Register B								page 86
0x11 (0x31)	USIPP	–	–	–	–	–	–	–	USIPOS	page 136
0x10 (0x30)	USIBR	USI Buffer Register								page 133
0x0F (0x2F)	USIDR	USI Data Register								page 132
0x0E (0x2E)	USISR	USISIF	USIOIF	USIPF	USIDC	USICNT3	USICNT2	USICNT1	USICNT0	page 133
0x0D (0x2D)	USICR	USISIE	USIOIE	USIWM1	USIWM0	USICS1	USICS0	USICLK	USITC	page 134
0x0C (0x2C)	GPOR2	General Purpose I/O Register 2								page 22
0x0B (0x2B)	GPOR1	General Purpose I/O Register 1								page 23
0x0A (0x2A)	GPOR0	General Purpose I/O Register 0								page 23
0x09 (0x29)	ACSRB	HSEL	HLEV	–	–	–	ACM2	ACM1	ACM0	page 140
0x08 (0x28)	ACSRA	ACD	ACBG	ACO	ACI	ACIE	ACME	ACIS1	ACIS0	page 139
0x07 (0x27)	ADMUX	REFS1	REFS0	ADLAR	MUX4	MUX3	MUX2	MUX1	MUX0	page 155
0x06 (0x26)	ADCSRA	ADEN	ADSC	ADATE	ADIF	ADIE	ADPS2	ADPS1	ADPS0	page 159
0x05 (0x25)	ADCH	ADC Data Register High Byte								page 160
0x04 (0x24)	ADCL	ADC Data Register Low Byte								page 160
0x03 (0x23)	ADCSRB	BIN	GSEL	–	REFS2	MUX5	ADTS2	ADTS1	ADTS0	page 161
0x02 (0x22)	DIDR1	ADC10D	ADC9D	ADC8D	ADC7D	–	–	–	–	page 162
0x01 (0x21)	DIDR0	ADC6D	ADC5D	ADC4D	ADC3D	AREFD	ADC2D	ADC1D	ADC0D	page 162
0x00 (0x20)	TCCR1E	–	–	OC1OE5	OC1OE4	OC1OE3	OC1OE2	OC1OE1	OC1OE0	page 119

- Note:
1. For compatibility with future devices, reserved bits should be written to zero if accessed. Reserved I/O memory addresses should never be written.
 2. I/O Registers within the address range 0x00 - 0x1F are directly bit-accessible using the SBI and CBI instructions. In these registers, the value of single bits can be checked by using the SBIS and SBIC instructions.
 3. Some of the Status Flags are cleared by writing a logical one to them. Note that, unlike most other AVRs, the CBI and SBI instructions will only operation the specified bit, and can therefore be used on registers containing such Status Flags. The CBI and SBI instructions work with registers 0x00 to 0x1F only.

22. Instruction Set Summary

Mnemonics	Operands	Description	Operation	Flags	#Clocks
ARITHMETIC AND LOGIC INSTRUCTIONS					
ADD	Rd, Rr	Add two Registers	$Rd \leftarrow Rd + Rr$	Z,C,N,V,H	1
ADC	Rd, Rr	Add with Carry two Registers	$Rd \leftarrow Rd + Rr + C$	Z,C,N,V,H	1
ADIW	Rdl,K	Add Immediate to Word	$Rdh:Rdl \leftarrow Rdh:Rdl + K$	Z,C,N,V,S	2
SUB	Rd, Rr	Subtract two Registers	$Rd \leftarrow Rd - Rr$	Z,C,N,V,H	1
SUBI	Rd, K	Subtract Constant from Register	$Rd \leftarrow Rd - K$	Z,C,N,V,H	1
SBC	Rd, Rr	Subtract with Carry two Registers	$Rd \leftarrow Rd - Rr - C$	Z,C,N,V,H	1
SBCI	Rd, K	Subtract with Carry Constant from Reg.	$Rd \leftarrow Rd - K - C$	Z,C,N,V,H	1
SBIW	Rdl,K	Subtract Immediate from Word	$Rdh:Rdl \leftarrow Rdh:Rdl - K$	Z,C,N,V,S	2
AND	Rd, Rr	Logical AND Registers	$Rd \leftarrow Rd \bullet Rr$	Z,N,V	1
ANDI	Rd, K	Logical AND Register and Constant	$Rd \leftarrow Rd \bullet K$	Z,N,V	1
OR	Rd, Rr	Logical OR Registers	$Rd \leftarrow Rd \vee Rr$	Z,N,V	1
ORI	Rd, K	Logical OR Register and Constant	$Rd \leftarrow Rd \vee K$	Z,N,V	1
EOR	Rd, Rr	Exclusive OR Registers	$Rd \leftarrow Rd \oplus Rr$	Z,N,V	1
COM	Rd	One's Complement	$Rd \leftarrow 0xFF - Rd$	Z,C,N,V	1
NEG	Rd	Two's Complement	$Rd \leftarrow 0x00 - Rd$	Z,C,N,V,H	1
SBR	Rd,K	Set Bit(s) in Register	$Rd \leftarrow Rd \vee K$	Z,N,V	1
CBR	Rd,K	Clear Bit(s) in Register	$Rd \leftarrow Rd \bullet (0xFF - K)$	Z,N,V	1
INC	Rd	Increment	$Rd \leftarrow Rd + 1$	Z,N,V	1
DEC	Rd	Decrement	$Rd \leftarrow Rd - 1$	Z,N,V	1
TST	Rd	Test for Zero or Minus	$Rd \leftarrow Rd \bullet Rd$	Z,N,V	1
CLR	Rd	Clear Register	$Rd \leftarrow Rd \oplus Rd$	Z,N,V	1
SER	Rd	Set Register	$Rd \leftarrow 0xFF$	None	1
BRANCH INSTRUCTIONS					
RJMP	k	Relative Jump	$PC \leftarrow PC + k + 1$	None	2
IJMP		Indirect Jump to (Z)	$PC \leftarrow Z$	None	2
RCALL	k	Relative Subroutine Call	$PC \leftarrow PC + k + 1$	None	3
ICALL		Indirect Call to (Z)	$PC \leftarrow Z$	None	3
RET		Subroutine Return	$PC \leftarrow STACK$	None	4
RETI		Interrupt Return	$PC \leftarrow STACK$	I	4
CPSE	Rd,Rr	Compare, Skip if Equal	if (Rd = Rr) $PC \leftarrow PC + 2$ or 3	None	1/2/3
CP	Rd,Rr	Compare	$Rd - Rr$	Z, N,V,C,H	1
CPC	Rd,Rr	Compare with Carry	$Rd - Rr - C$	Z, N,V,C,H	1
CPI	Rd,K	Compare Register with Immediate	$Rd - K$	Z, N,V,C,H	1
SBRC	Rr, b	Skip if Bit in Register Cleared	if (Rr(b)=0) $PC \leftarrow PC + 2$ or 3	None	1/2/3
SBRS	Rr, b	Skip if Bit in Register is Set	if (Rr(b)=1) $PC \leftarrow PC + 2$ or 3	None	1/2/3
SBIC	P, b	Skip if Bit in I/O Register Cleared	if (P(b)=0) $PC \leftarrow PC + 2$ or 3	None	1/2/3
SBIS	P, b	Skip if Bit in I/O Register is Set	if (P(b)=1) $PC \leftarrow PC + 2$ or 3	None	1/2/3
BRBS	s, k	Branch if Status Flag Set	if (SREG(s) = 1) then $PC \leftarrow PC + k + 1$	None	1/2
BRBC	s, k	Branch if Status Flag Cleared	if (SREG(s) = 0) then $PC \leftarrow PC + k + 1$	None	1/2
BREQ	k	Branch if Equal	if (Z = 1) then $PC \leftarrow PC + k + 1$	None	1/2
BRNE	k	Branch if Not Equal	if (Z = 0) then $PC \leftarrow PC + k + 1$	None	1/2
BRCS	k	Branch if Carry Set	if (C = 1) then $PC \leftarrow PC + k + 1$	None	1/2
BRCC	k	Branch if Carry Cleared	if (C = 0) then $PC \leftarrow PC + k + 1$	None	1/2
BRSH	k	Branch if Same or Higher	if (C = 0) then $PC \leftarrow PC + k + 1$	None	1/2
BRLO	k	Branch if Lower	if (C = 1) then $PC \leftarrow PC + k + 1$	None	1/2
BRMI	k	Branch if Minus	if (N = 1) then $PC \leftarrow PC + k + 1$	None	1/2
BRPL	k	Branch if Plus	if (N = 0) then $PC \leftarrow PC + k + 1$	None	1/2
BRGE	k	Branch if Greater or Equal, Signed	if (N $\oplus$ V = 0) then $PC \leftarrow PC + k + 1$	None	1/2
BRLT	k	Branch if Less Than Zero, Signed	if (N $\oplus$ V = 1) then $PC \leftarrow PC + k + 1$	None	1/2
BRHS	k	Branch if Half Carry Flag Set	if (H = 1) then $PC \leftarrow PC + k + 1$	None	1/2
BRHC	k	Branch if Half Carry Flag Cleared	if (H = 0) then $PC \leftarrow PC + k + 1$	None	1/2
BRTS	k	Branch if T Flag Set	if (T = 1) then $PC \leftarrow PC + k + 1$	None	1/2
BRTC	k	Branch if T Flag Cleared	if (T = 0) then $PC \leftarrow PC + k + 1$	None	1/2
BRVS	k	Branch if Overflow Flag is Set	if (V = 1) then $PC \leftarrow PC + k + 1$	None	1/2
BRVC	k	Branch if Overflow Flag is Cleared	if (V = 0) then $PC \leftarrow PC + k + 1$	None	1/2
BRIE	k	Branch if Interrupt Enabled	if (I = 1) then $PC \leftarrow PC + k + 1$	None	1/2
BRID	k	Branch if Interrupt Disabled	if (I = 0) then $PC \leftarrow PC + k + 1$	None	1/2
BIT AND BIT-TEST INSTRUCTIONS					
SBI	P,b	Set Bit in I/O Register	$I/O(P,b) \leftarrow 1$	None	2
CBI	P,b	Clear Bit in I/O Register	$I/O(P,b) \leftarrow 0$	None	2
LSL	Rd	Logical Shift Left	$Rd(n+1) \leftarrow Rd(n), Rd(0) \leftarrow 0$	Z,C,N,V	1
LSR	Rd	Logical Shift Right	$Rd(n) \leftarrow Rd(n+1), Rd(7) \leftarrow 0$	Z,C,N,V	1
ROL	Rd	Rotate Left Through Carry	$Rd(0) \leftarrow C, Rd(n+1) \leftarrow Rd(n), C \leftarrow Rd(7)$	Z,C,N,V	1
ROR	Rd	Rotate Right Through Carry	$Rd(7) \leftarrow C, Rd(n) \leftarrow Rd(n+1), C \leftarrow Rd(0)$	Z,C,N,V	1

Mnemonics	Operands	Description	Operation	Flags	#Clocks
ASR	Rd	Arithmetic Shift Right	$Rd(n) \leftarrow Rd(n+1), n=0..6$	Z,C,N,V	1
SWAP	Rd	Swap Nibbles	$Rd(3..0) \leftarrow Rd(7..4), Rd(7..4) \leftarrow Rd(3..0)$	None	1
BSET	s	Flag Set	$SREG(s) \leftarrow 1$	SREG(s)	1
BCLR	s	Flag Clear	$SREG(s) \leftarrow 0$	SREG(s)	1
BST	Rr, b	Bit Store from Register to T	$T \leftarrow Rr(b)$	T	1
BLD	Rd, b	Bit load from T to Register	$Rd(b) \leftarrow T$	None	1
SEC		Set Carry	$C \leftarrow 1$	C	1
CLC		Clear Carry	$C \leftarrow 0$	C	1
SEN		Set Negative Flag	$N \leftarrow 1$	N	1
CLN		Clear Negative Flag	$N \leftarrow 0$	N	1
SEZ		Set Zero Flag	$Z \leftarrow 1$	Z	1
CLZ		Clear Zero Flag	$Z \leftarrow 0$	Z	1
SEI		Global Interrupt Enable	$I \leftarrow 1$	I	1
CLI		Global Interrupt Disable	$I \leftarrow 0$	I	1
SES		Set Signed Test Flag	$S \leftarrow 1$	S	1
CLS		Clear Signed Test Flag	$S \leftarrow 0$	S	1
SEV		Set Twos Complement Overflow.	$V \leftarrow 1$	V	1
CLV		Clear Twos Complement Overflow	$V \leftarrow 0$	V	1
SET		Set T in SREG	$T \leftarrow 1$	T	1
CLT		Clear T in SREG	$T \leftarrow 0$	T	1
SEH		Set Half Carry Flag in SREG	$H \leftarrow 1$	H	1
CLH		Clear Half Carry Flag in SREG	$H \leftarrow 0$	H	1
DATA TRANSFER INSTRUCTIONS					
MOV	Rd, Rr	Move Between Registers	$Rd \leftarrow Rr$	None	1
MOVW	Rd, Rr	Copy Register Word	$Rd+1:Rd \leftarrow Rr+1:Rr$	None	1
LDI	Rd, K	Load Immediate	$Rd \leftarrow K$	None	1
LD	Rd, X	Load Indirect	$Rd \leftarrow (X)$	None	2
LD	Rd, X+	Load Indirect and Post-Inc.	$Rd \leftarrow (X), X \leftarrow X + 1$	None	2
LD	Rd, -X	Load Indirect and Pre-Dec.	$X \leftarrow X - 1, Rd \leftarrow (X)$	None	2
LD	Rd, Y	Load Indirect	$Rd \leftarrow (Y)$	None	2
LD	Rd, Y+	Load Indirect and Post-Inc.	$Rd \leftarrow (Y), Y \leftarrow Y + 1$	None	2
LD	Rd, -Y	Load Indirect and Pre-Dec.	$Y \leftarrow Y - 1, Rd \leftarrow (Y)$	None	2
LDD	Rd, Y+q	Load Indirect with Displacement	$Rd \leftarrow (Y + q)$	None	2
LD	Rd, Z	Load Indirect	$Rd \leftarrow (Z)$	None	2
LD	Rd, Z+	Load Indirect and Post-Inc.	$Rd \leftarrow (Z), Z \leftarrow Z + 1$	None	2
LD	Rd, -Z	Load Indirect and Pre-Dec.	$Z \leftarrow Z - 1, Rd \leftarrow (Z)$	None	2
LDD	Rd, Z+q	Load Indirect with Displacement	$Rd \leftarrow (Z + q)$	None	2
LDS	Rd, k	Load Direct from SRAM	$Rd \leftarrow (k)$	None	2
ST	X, Rr	Store Indirect	$(X) \leftarrow Rr$	None	2
ST	X+, Rr	Store Indirect and Post-Inc.	$(X) \leftarrow Rr, X \leftarrow X + 1$	None	2
ST	-X, Rr	Store Indirect and Pre-Dec.	$X \leftarrow X - 1, (X) \leftarrow Rr$	None	2
ST	Y, Rr	Store Indirect	$(Y) \leftarrow Rr$	None	2
ST	Y+, Rr	Store Indirect and Post-Inc.	$(Y) \leftarrow Rr, Y \leftarrow Y + 1$	None	2
ST	-Y, Rr	Store Indirect and Pre-Dec.	$Y \leftarrow Y - 1, (Y) \leftarrow Rr$	None	2
STD	Y+q, Rr	Store Indirect with Displacement	$(Y + q) \leftarrow Rr$	None	2
ST	Z, Rr	Store Indirect	$(Z) \leftarrow Rr$	None	2
ST	Z+, Rr	Store Indirect and Post-Inc.	$(Z) \leftarrow Rr, Z \leftarrow Z + 1$	None	2
ST	-Z, Rr	Store Indirect and Pre-Dec.	$Z \leftarrow Z - 1, (Z) \leftarrow Rr$	None	2
STD	Z+q, Rr	Store Indirect with Displacement	$(Z + q) \leftarrow Rr$	None	2
STS	k, Rr	Store Direct to SRAM	$(k) \leftarrow Rr$	None	2
LPM		Load Program Memory	$R0 \leftarrow (Z)$	None	3
LPM	Rd, Z	Load Program Memory	$Rd \leftarrow (Z)$	None	3
LPM	Rd, Z+	Load Program Memory and Post-Inc	$Rd \leftarrow (Z), Z \leftarrow Z + 1$	None	3
SPM		Store Program Memory	$(Z) \leftarrow R1:R0$	None	
IN	Rd, P	In Port	$Rd \leftarrow P$	None	1
OUT	P, Rr	Out Port	$P \leftarrow Rr$	None	1
PUSH	Rr	Push Register on Stack	$STACK \leftarrow Rr$	None	2
POP	Rd	Pop Register from Stack	$Rd \leftarrow STACK$	None	2
MCU CONTROL INSTRUCTIONS					
NOP		No Operation		None	1
SLEEP		Sleep	(see specific descr. for Sleep function)	None	1
WDR		Watchdog Reset	(see specific descr. for WDR/Timer)	None	1
BREAK		Break	For On-chip Debug Only	None	N/A

23. Ordering Information

23.1 ATtiny261 - Mature

Speed (MHz) ⁽³⁾	Power Supply (V)	Ordering Code ⁽⁴⁾⁽⁵⁾	Package ⁽²⁾	Operational Range
10	1.8 - 5.5	ATtiny261V-10MU ATtiny261V-10MUR ATtiny261V-10PU ATtiny261V-10SU ATtiny261V-10SUR	32M1-A 32M1-A 20P3 20S2 20S2	Industrial (-40°C to +85°C) ⁽¹⁾
20	2.7 - 5.5	ATtiny261-20MU ATtiny261-20MUR ATtiny261-20PU ATtiny261-20SU ATtiny261-20SUR	32M1-A 32M1-A 20P3 20S2 20S2	Industrial (-40°C to +85°C) ⁽¹⁾

- Notes:
1. These devices can also be supplied in wafer form. Please contact your local Atmel sales office for detailed ordering information and minimum quantities.
 2. All packages are Pb-free, halide-free and fully green and they comply with the European directive for Restriction of Hazardous Substances (RoHS).
 3. For Speed vs. V_{CC} , see [Figure 19.3 on page 188](#).
 4. Code indicators:
 - U: matte tin
 - R: tape & reel
 5. Mature devices, replaced by ATtiny261A.

Package Type	
32M1-A	32-pad, 5 x 5 x 1.0 mm Body, Lead Pitch 0.50 mm, Micro Lead Frame Package (MLF)
20P3	20-lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)
20S2	20-lead, 0.300" Wide, Plastic Gull Wing Smal Outline Package (SOIC)

23.2 ATtiny461

Speed (MHz) ⁽³⁾	Power Supply (V)	Ordering Code ⁽⁴⁾	Package ⁽²⁾	Operational Range
10	1.8 - 5.5	ATtiny461V-10MU ATtiny461V-10MUR ATtiny461V-10PU ATtiny461V-10SU ATtiny461V-10SUR	32M1-A 32M1-A 20P3 20S2 20S2	Industrial (-40°C to +85°C) ⁽¹⁾
20	2.7 - 5.5	ATtiny461-20MU ATtiny461-20MUR ATtiny461-20PU ATtiny461-20SU ATtiny461-20SUR	32M1-A 32M1-A 20P3 20S2 20S2	Industrial (-40°C to +85°C) ⁽¹⁾

- Notes:
1. These devices can also be supplied in wafer form. Please contact your local Atmel sales office for detailed ordering information and minimum quantities.
 2. All packages are Pb-free, halide-free and fully green and they comply with the European directive for Restriction of Hazardous Substances (RoHS).
 3. For Speed vs. V_{CC} , see [Figure 19.3 on page 188](#).
 4. Code indicators:
 - U: matte tin
 - R: tape & reel

Package Type	
32M1-A	32-pad, 5 x 5 x 1.0 mm Body, Lead Pitch 0.50 mm, Micro Lead Frame Package (MLF)
20P3	20-lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)
20S2	20-lead, 0.300" Wide, Plastic Gull Wing Small Outline Package (SOIC)

23.3 ATtiny861

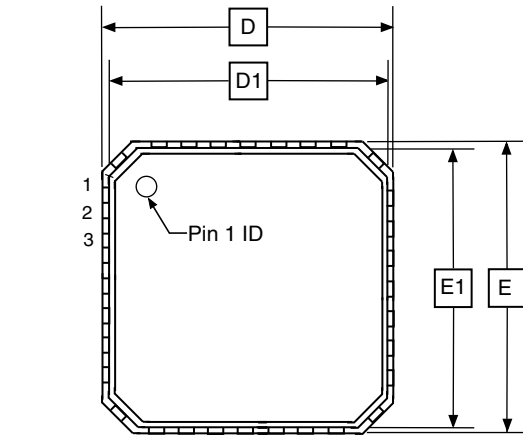
Speed (MHz) ⁽³⁾	Power Supply (V)	Ordering Code ⁽⁴⁾	Package ⁽²⁾	Operational Range
10	1.8 - 5.5	ATtiny861V-10MU ATtiny861V-10MUR ATtiny861V-10PU ATtiny861V-10SU ATtiny861V-10SUR	32M1-A 32M1-A 20P3 20S2 20S2	Industrial (-40°C to +85°C) ⁽¹⁾
20	2.7 - 5.5	ATtiny861-20MU ATtiny861-20MUR ATtiny861-20PU ATtiny861-20SU ATtiny861-20SUR	32M1-A 32M1-A 20P3 20S2 20S2	Industrial (-40°C to +85°C) ⁽¹⁾

- Notes:
1. These devices can also be supplied in wafer form. Please contact your local Atmel sales office for detailed ordering information and minimum quantities.
 2. All packages are Pb-free, halide-free and fully green and they comply with the European directive for Restriction of Hazardous Substances (RoHS).
 3. For Speed vs. V_{CC} , see [Figure 19.3 on page 188](#).
 4. Code indicators:
 - U: matte tin
 - R: tape & reel

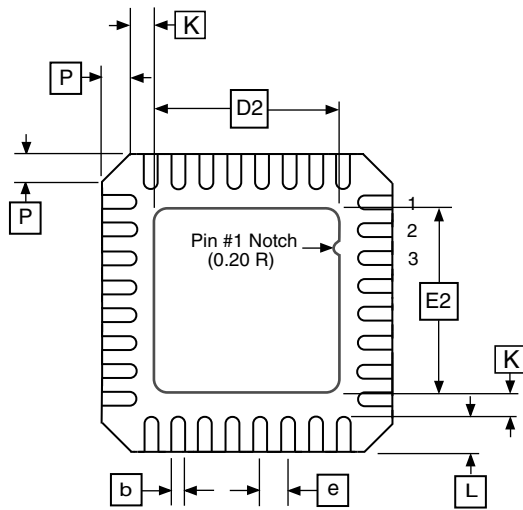
Package Type	
32M1-A	32-pad, 5 x 5 x 1.0 mm Body, Lead Pitch 0.50 mm, Micro Lead Frame Package (MLF)
20P3	20-lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)
20S2	20-lead, 0.300" Wide, Plastic Gull Wing Small Outline Package (SOIC)

24. Packaging Information

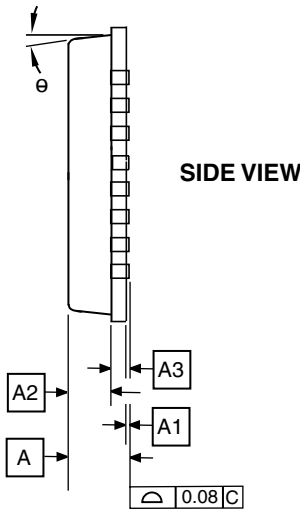
24.1 32M1-A



TOP VIEW



BOTTOM VIEW



SIDE VIEW

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	0.90	1.00	
A1	—	0.02	0.05	
A2	—	0.65	1.00	
A3	0.20 REF			
b	0.18	0.23	0.30	
D	5.00 BSC			
D1	4.75 BSC			
D2	2.95	3.10	3.25	
E	5.00 BSC			
E1	4.75BSC			
E2	2.95	3.10	3.25	
e	0.50 BSC			
L	0.30	0.40	0.50	
P	—	—	0.60	
θ	—	—	12°	
K	0.20	—	—	

Note: JEDEC Standard MO-220, Fig. 2 (Anvil Singulation), VHHD-2.

8/19/04



2325 Orchard Parkway
San Jose, CA 95131

TITLE

32M1-A, 32-pad, 5 x 5 x 1.0 mm Body, Lead Pitch 0.50 mm,
3.10 mm Exposed Pad, Micro Lead Frame Package (MLF)

DRAWING NO.

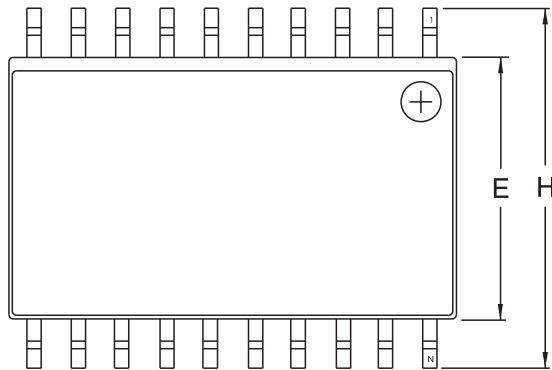
32M1-A

REV.

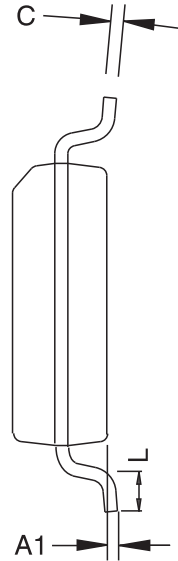
D

24.2 20P3

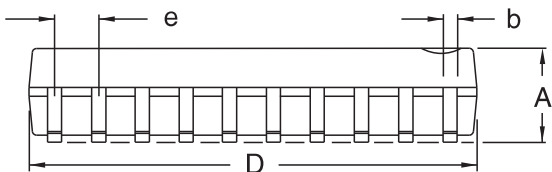
24.3 20S2



Top View



End View



Side View

COMMON DIMENSIONS
(Unit of Measure – mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	2.35		2.65	
A1	0.10		0.30	
b	0.33		0.51	4
C	0.23		0.32	
D	12.60		13.00	1
E	7.40		7.60	2
H	10.00		10.65	
L	0.40		1.27	3
e	1.27 BSC			

- Notes.
1. This drawing is for general information only; refer to JEDEC Drawing MS-013, Variation AC for additional information.
 2. Dimension 'D' does not include mold Flash, protrusions or gate burrs. Mold Flash, protrusions and gate burrs shall not exceed 0.15 mm (0.006") per side.
 3. Dimension 'E' does not include inter-lead Flash or protrusion. Inter-lead Flash and protrusions shall not exceed 0.25 mm (0.010") per side.
 4. 'L' is the length of the terminal for soldering to a substrate.
 5. The lead width 'b', as measured 0.36 mm (0.014") or greater above the seating plane, shall not exceed a maximum value of 0.61 mm (0.024") per side.



2325 Orchard Parkway
San Jose, CA 95131

TITLE

20S2, 20-lead, 0.300" Wide Body, Plastic Gull Wing Small Outline Package (SOIC)

DRAWING NO.

20S2

REV.

B

25. Errata

25.1 Errata ATtiny261

The revision letter in this section refers to the revision of the ATtiny261 device.

25.1.1 Rev A

No known errata.

25.2 Errata ATtiny461

The revision letter in this section refers to the revision of the ATtiny461 device.

25.2.1 Rev B

Yield improvement. No known errata.

25.2.2 Rev A

No known errata.

25.3 Errata ATtiny861

The revision letter in this section refers to the revision of the ATtiny861 device.

25.3.1 Rev B

No known errata.

25.3.2 Rev A

Not sampled.

26. Datasheet Revision History

Please note that the referring page numbers in this section refer to the complete document.

26.1 Rev. 2588F – 06/13

1. ATtiny261 changed status to "Mature".

26.2 Rev. 2588E – 08/10

1. Added tape and reel in ["Ordering Information" on page 227](#).
2. Clarified [Section 6.4 "Clock Output Buffer" on page 32](#).
3. Removed text "Not recommended for new designs" from cover page.

26.3 Rev. 2588D – 06/10

1. Removed "Preliminary" from cover page.
2. Added clarification before [Table 6-10, "Capacitance for Low-Frequency Crystal Oscillator," on page 29](#).
3. Updated [Figure 15-1 "Analog to Digital Converter Block Schematic" on page 143](#), changed INTERNAL 1.18V REFERENCE to 1.1V.
4. Updated [Table 18-8, "No. of Words in a Page and No. of Pages in the EEPROM," on page 173](#), No. of Pages from 64 to 32 for ATtiny261.
5. Adjusted notes in [Table 19-1, "DC Characteristics. TA = -40°C to +85°C, VCC = 1.8V to 5.5V \(unless otherwise noted\),," on page 187](#).

26.4 Rev. 2588C – 10/09

1. Updated document template. Re-arranged some sections.
2. Changed device status to "Not Recommended for New Designs".
3. Added Sections:
 - ["Data Retention" on page 6](#)
 - ["Clock Sources" on page 25](#)
 - ["Low Level Interrupt" on page 51](#)
 - ["Prescaling and Conversion Timing" on page 145](#)
 - ["Clock speed considerations" on page 131](#)
4. Updated Sections:
 - ["Code Examples" on page 6](#)
 - ["High-Frequency PLL Clock" on page 26](#)
 - ["Normal Mode" on page 99](#)
 - ["Features" on page 142](#)
 - ["Temperature Measurement" on page 154](#)
 - ["Limitations of debugWIRE" on page 164](#)
 - [Step 1. on page 174](#)
 - ["Programming the Flash" on page 180](#)
 - ["System and Reset Characteristics" on page 190](#)
5. Added Figures:
 - ["Flash Programming Waveforms" on page 182](#)

- “Reset Pin Output Voltage vs. Sink Current (VCC = 3V)” on page 209
- “Reset Pin Output Voltage vs. Sink Current (VCC = 3V)” on page 209
- “Reset Pin Output Voltage vs. Sink Current (VCC = 3V)” on page 209
- “Reset Pin Output Voltage vs. Sink Current (VCC = 3V)” on page 209
- “Bandgap Voltage vs. Supply Voltage (VCC).” on page 216
- 6. Updated Figures:
 - “Block Diagram” on page 4
 - “Clock Distribution” on page 24
- 7. Added Table:
 - “Capacitance for Low-Frequency Crystal Oscillator” on page 29
- 8. Updated Tables:
 - “Start-up Times for the Internal Calibrated RC Oscillator Clock Selection” on page 28
 - “Start-up Times for the 128 kHz Internal Oscillator” on page 29
 - “Active Clock Domains and Wake-up Sources in Different Sleep Modes” on page 36
 - “Serial Programming Characteristics, TA = -40°C to +85°C, VCC = 1.8 - 5.5V (Unless Otherwise Noted)” on page 193
- 9. Updated Register Descriptions:
 - “TCCR1A – Timer/Counter1 Control Register A” on page 112
 - “TCCR1C – Timer/Counter1 Control Register C” on page 117
 - “ADMUX – ADC Multiplexer Selection Register” on page 155
- 10. Updated assembly program example in section “Write” on page 17.
- 11. Updated “DC Characteristics. TA = -40°C to +85°C, VCC = 1.8V to 5.5V (unless otherwise noted).” on page 187.

26.5 Rev. 2588B – 11/06

1. Updated “Ordering Information” on page 227.
2. Updated “Packaging Information” on page 231.

26.6 Rev. 2588A – 10/06

1. Initial Revision.

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